

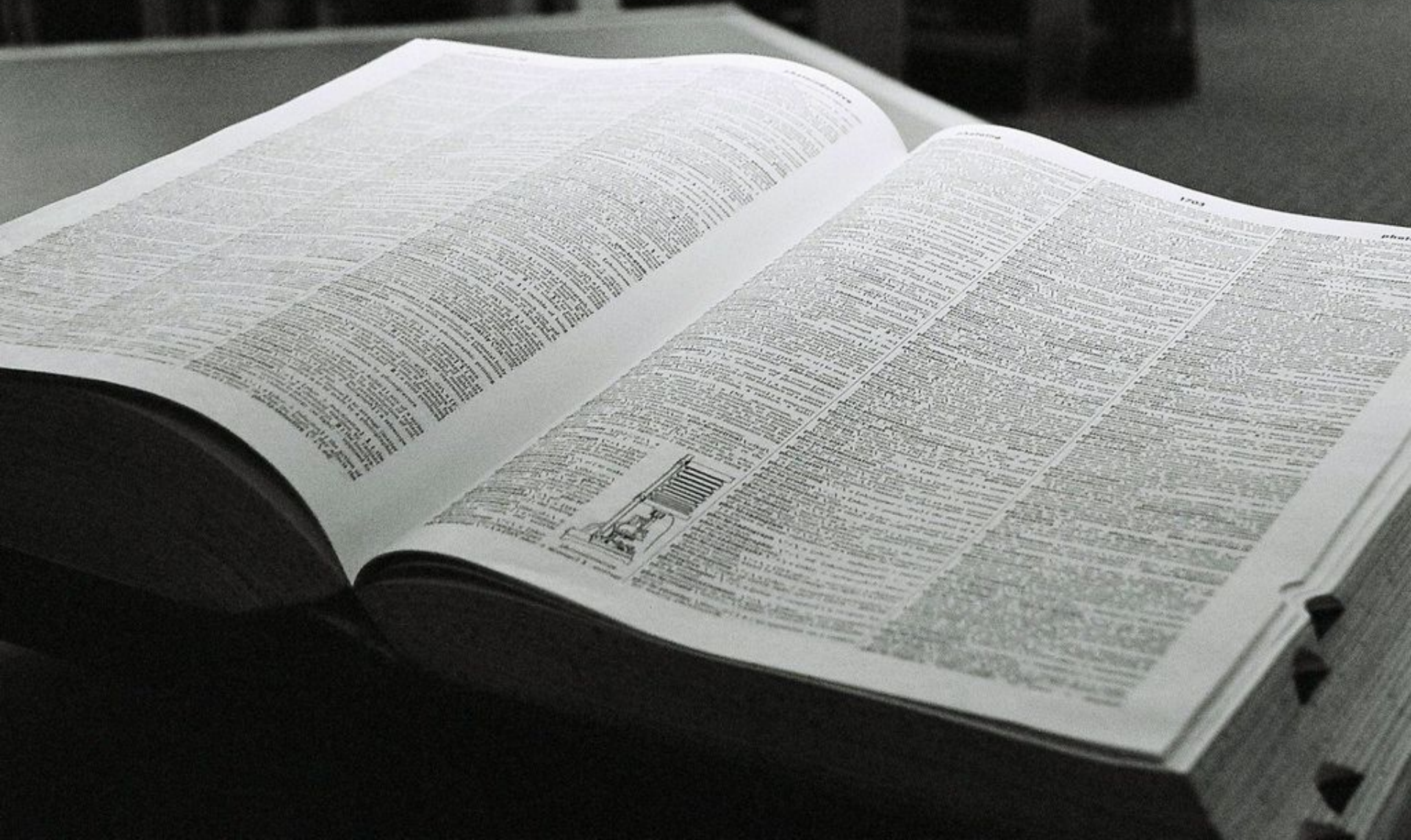


Beyond CMOS

IU.NET in search of the next switch

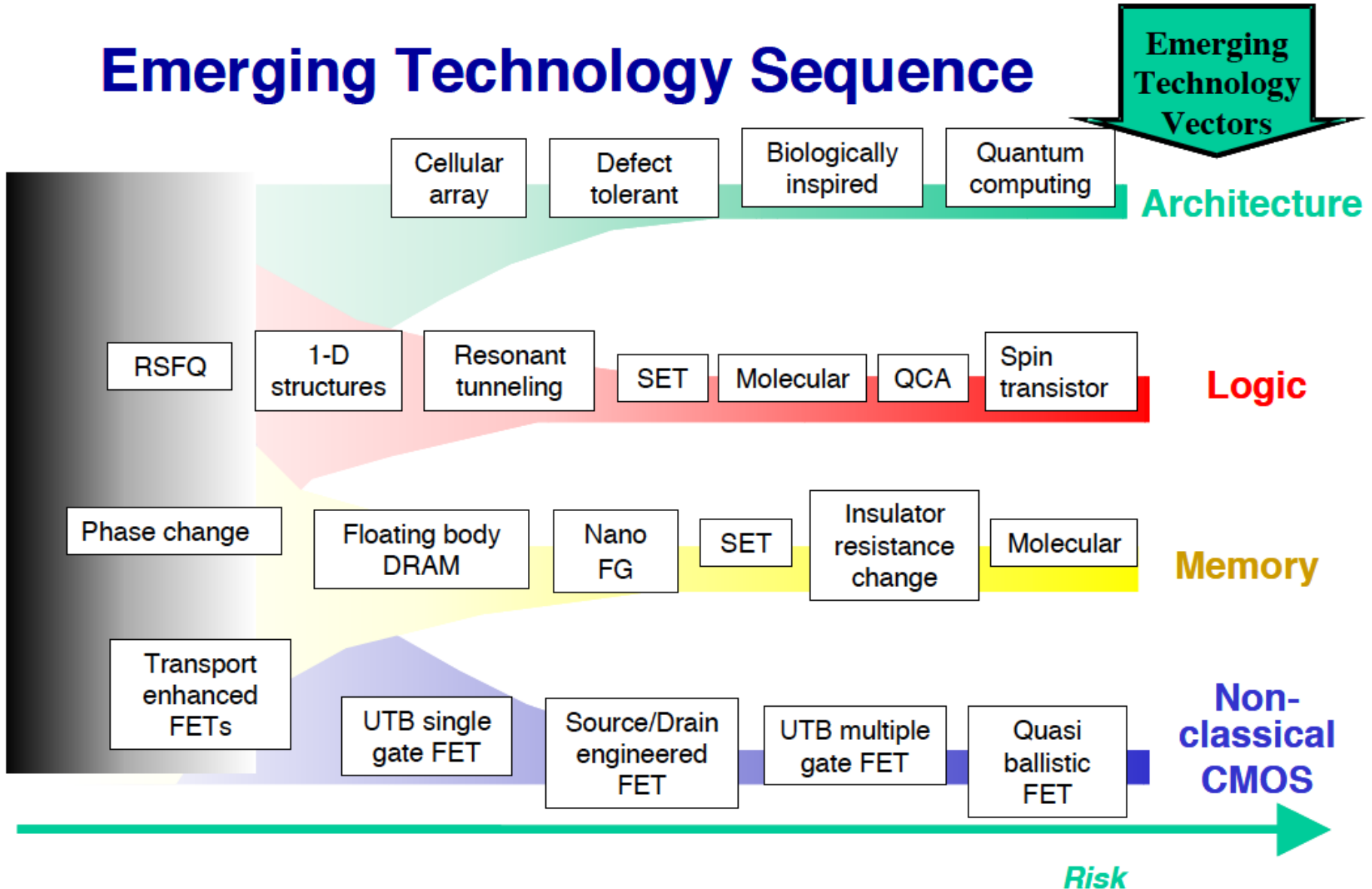
Giuseppe Iannaccone, U. Pisa

... “Beyond CMOS” ...



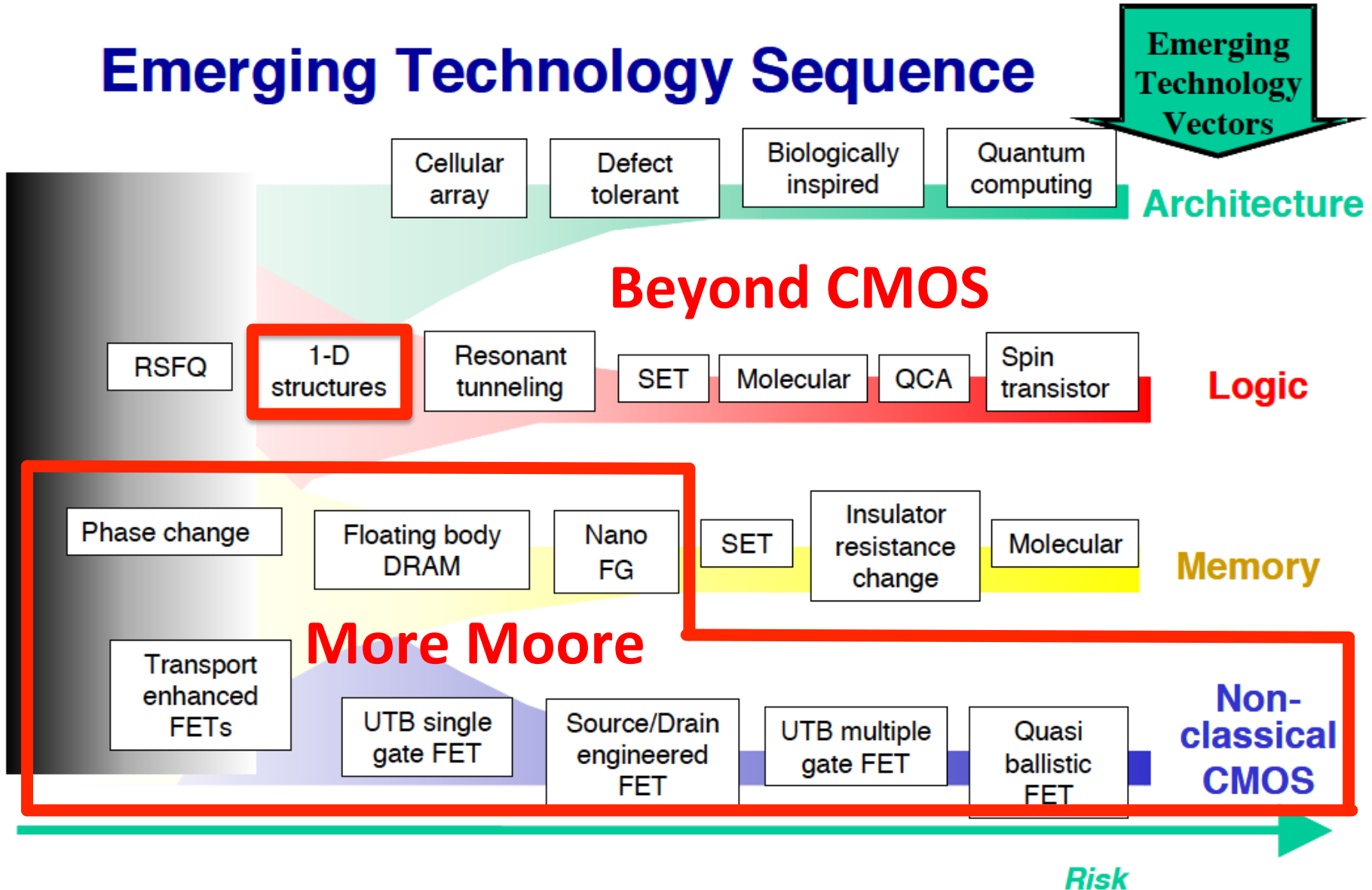
From ITRS 2003

Emerging Technology Sequence



From ITRS 2003 (\rightarrow 22 nm)

Emerging Technology Sequence



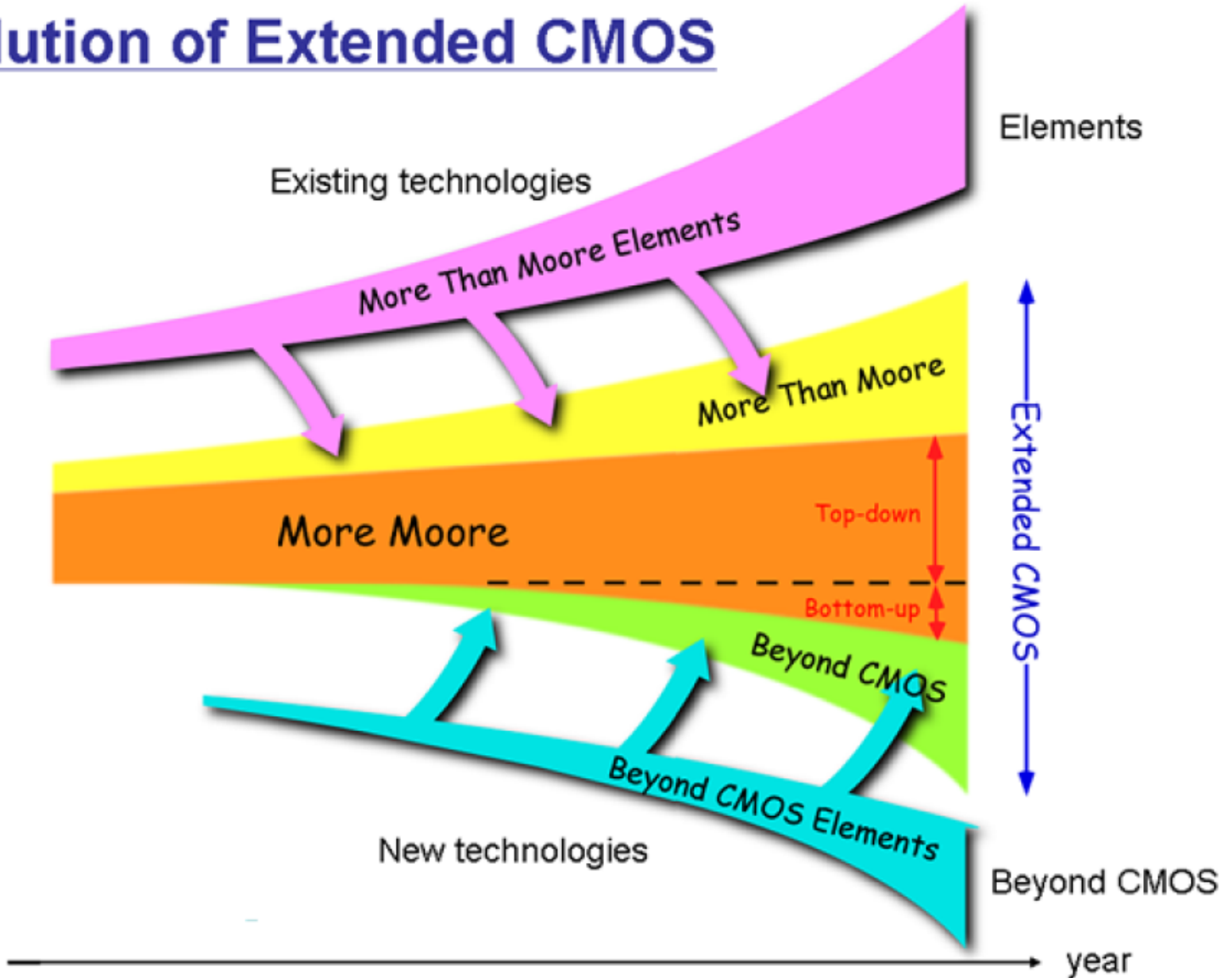
First Call of FP7 (dec 2006)

After ENIAC SRA 2005

- **“More Moore”**:
beyond 32 nm, digital SoCs
- **“More than Moore”**:
heterogeneous SoPs
- **“Beyond CMOS”**:
non-FET-based logic and memory (and their integration with CMOS).

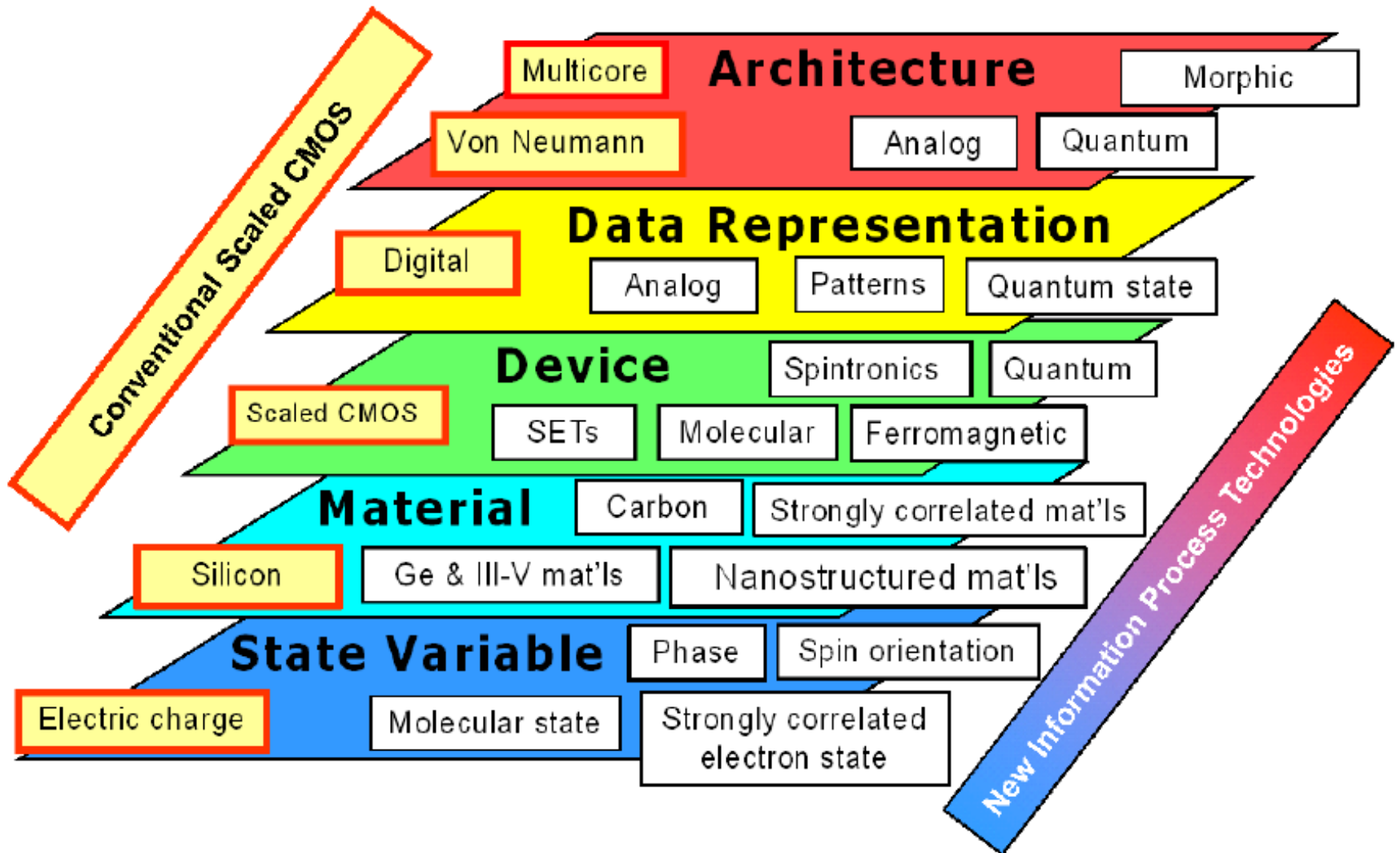
From ITRS 2013

Evolution of Extended CMOS



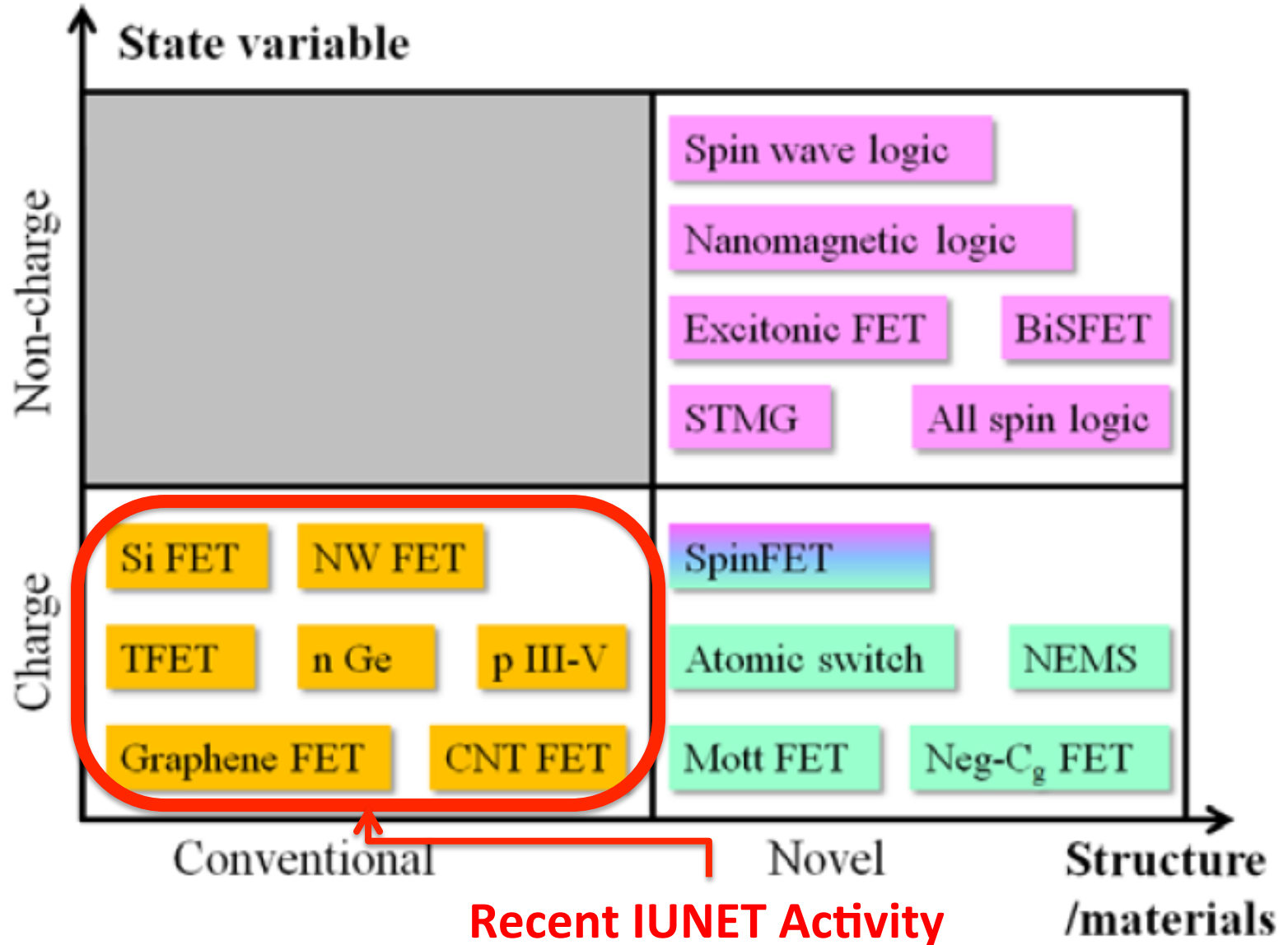
From ITRS 2013

A Taxonomy for Nano Information Processing Technologies



From ITRS 2013

Taxonomy of options for emerging logic devices





...We have nothing Beyond CMOS...

Are we already beyond CMOS?

2001 - 130 nm
Silicon
SiO₂ - poly
Planar [2D]

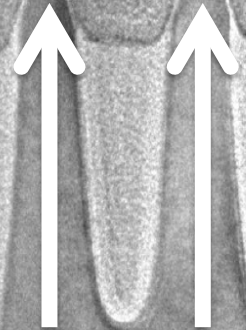
140nm

Lg = 70nm

:CoSi₂ ○

2014 - 14 nm
Strained Si/Ge
HKMG - 3D

42 nm



14 nm

FINFETs

IUNET Projects with focus on “““Beyond CMOS””” (logic)

- Nanosil (FP6):
 - Nanowire Transistors, graphene, Tunnel FETs
- GRAND (FP7):
 - Graphene-based devices: GFETs and GNR-FETs
- Steeper (FP7):
 - Tunnel FETs
- GRADE (FP7):
 - Graphene-based devices: GFETs and GBTs

Also 1
SpinFET
example

Non
FET

Pre-IUNET: Quadrant (FP4), Answers, NanoTCAD (FP5), Sinano (FP6)

QCA

QCA

SET
Single Molecule

SpinFET

Main role of IUNET in “Beyond CMOS” projects

Use modeling and simulation to

- *propose **new device concepts**,*
- ***Explore** technology options,*
- ***Benchmark** and optimize device and technology proposals*

Main role of IUNET in “Beyond CMOS”

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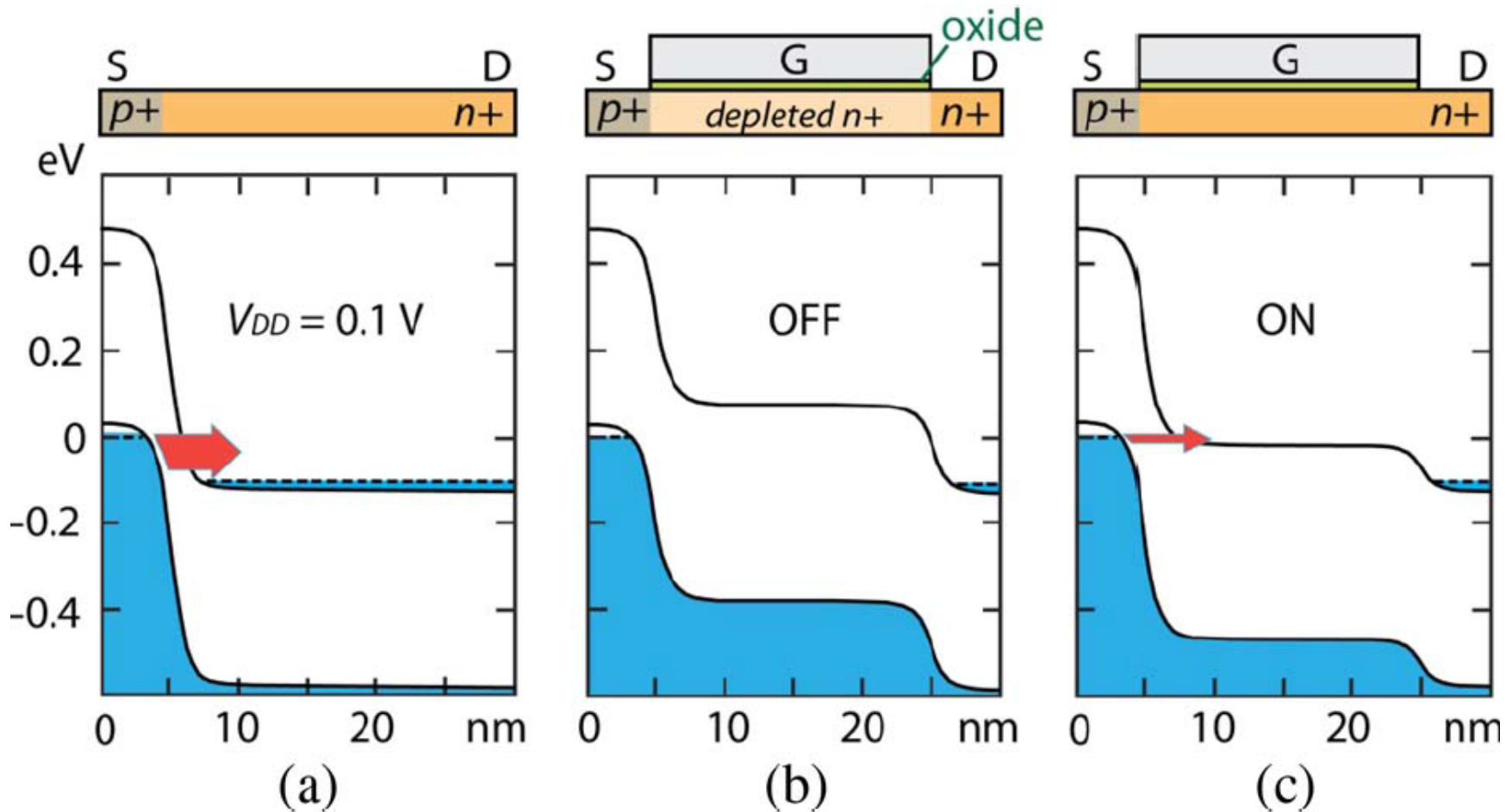
True multidisciplinarity
required:
Engineering + Physics +
Chemistry

*We should try to be
competitive also in
characterization and
fabrication*

TFET principle of operation

S. Banerjee et al. EDL 1987 (TI)

W. Hansch, several papers in 2000-2003 (TUM)



Credit: Figure from A. C. Seabaugh, Q. Zhang, Proc. IEEE 98, 2095 (2010)

Tunnel FET

- Main promise: **low V_{DD} operation \rightarrow Low DPI**
- Small gap is an advantage \rightarrow higher I_{ON}

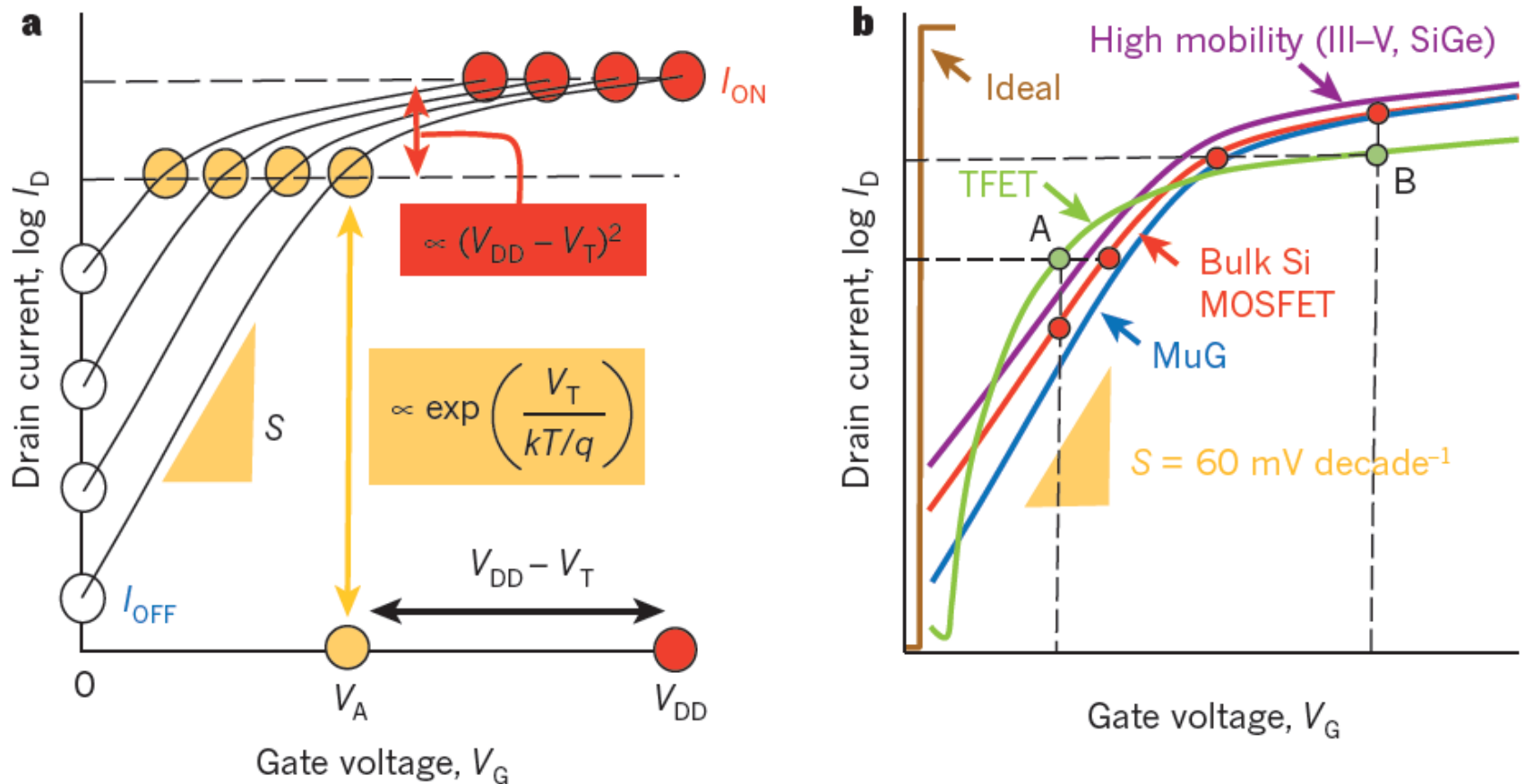
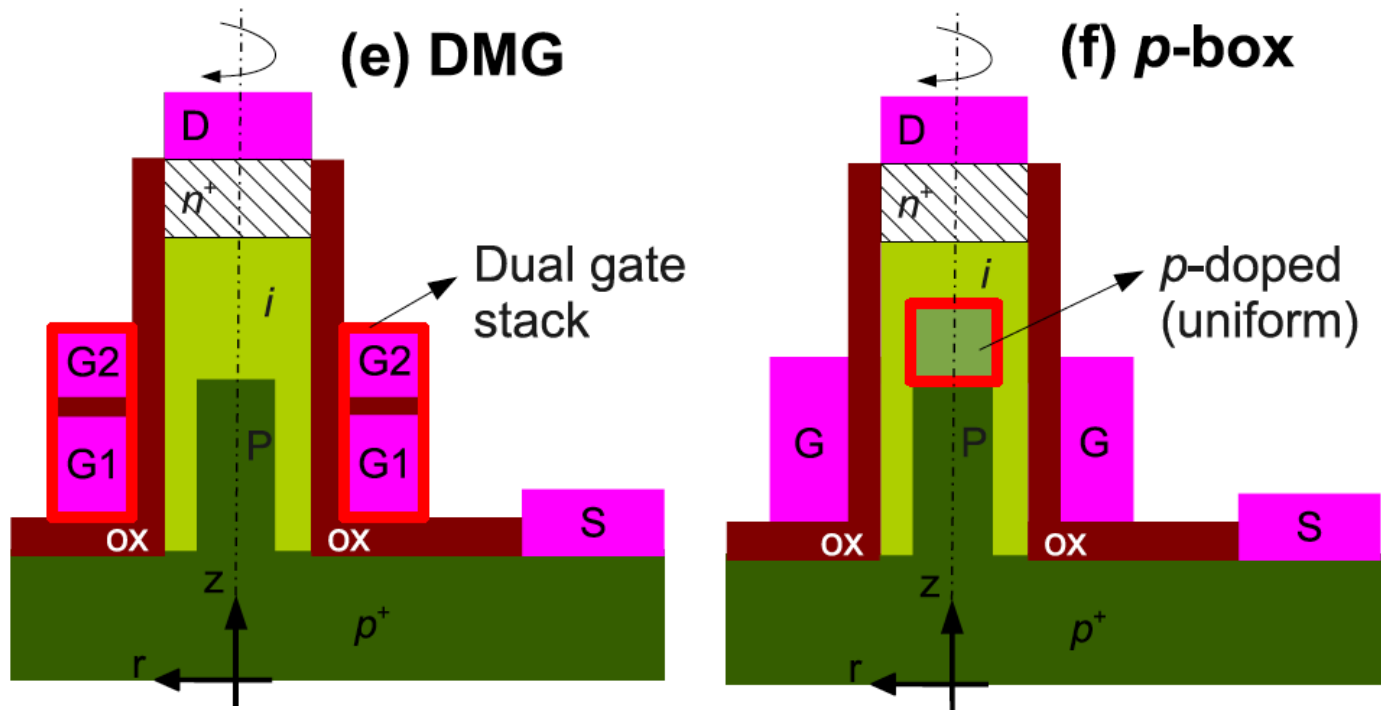


Figure Credits: Ionescu et al. Nature 479, 329 (2011)

InAs TFET optimization to meet ITRS 2020

Beneventi et al. IEEE TED 61, 778 (2014) - BOLOGNA

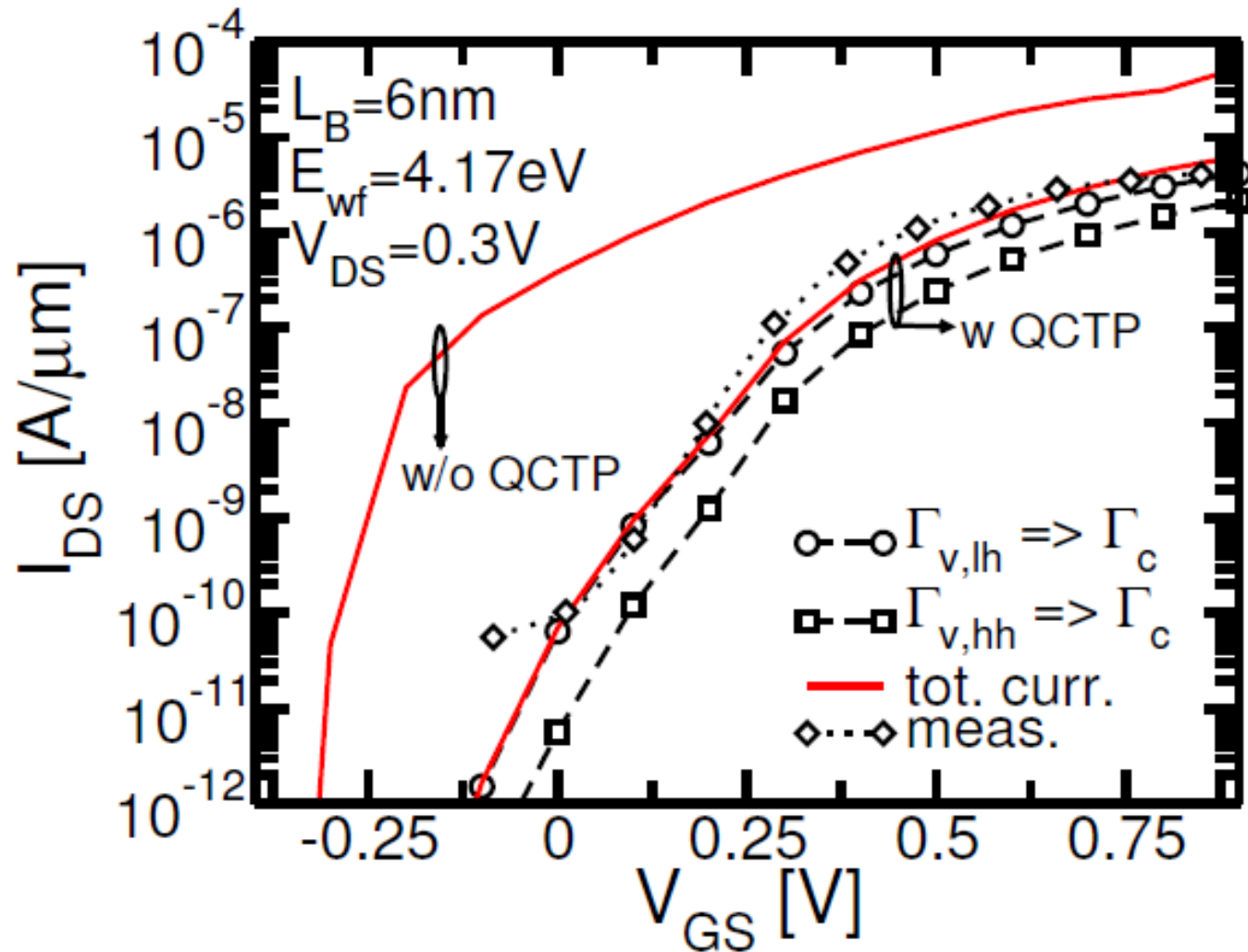
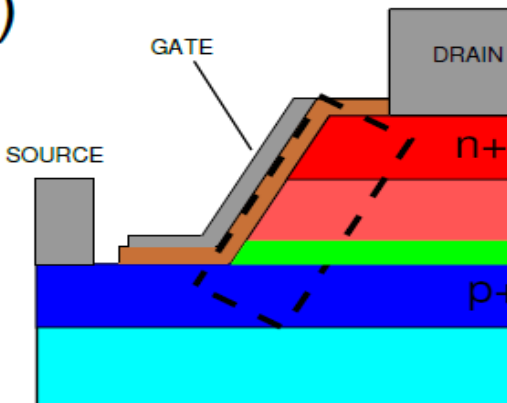


spec	ITRS 2020			OPT-DMG		
	LSTP	LOP	HP	LSTP	LOP	HP
V_{DD} [V]	0.67	0.53	0.68	0.5	0.5	0.5
I_{OFF} [nA/ μ m]	0.01	5	100	0.01	5	100
I_{ON} [mA/ μ m]	0.600	0.784	1.916	1.322	1.650	1.985
I_{ON}/I_{OFF}	6.0×10^7	1.5×10^5	1.9×10^4	1.3×10^8	3.3×10^5	2×10^4
τ (multi-gate) [ps]	0.58	0.35	0.19	0.94	0.68	0.31

Heterojunction III-V TFET

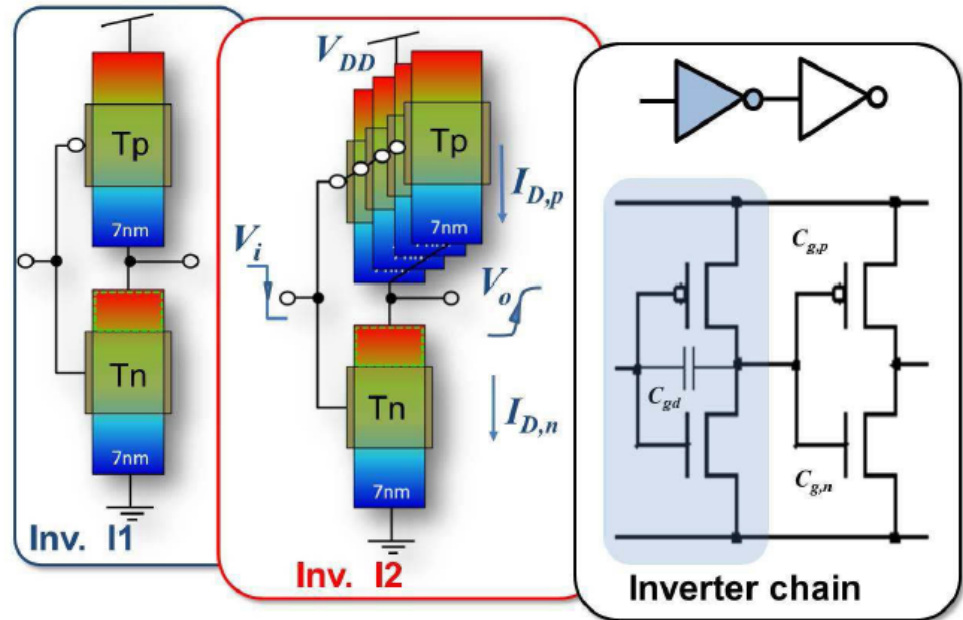
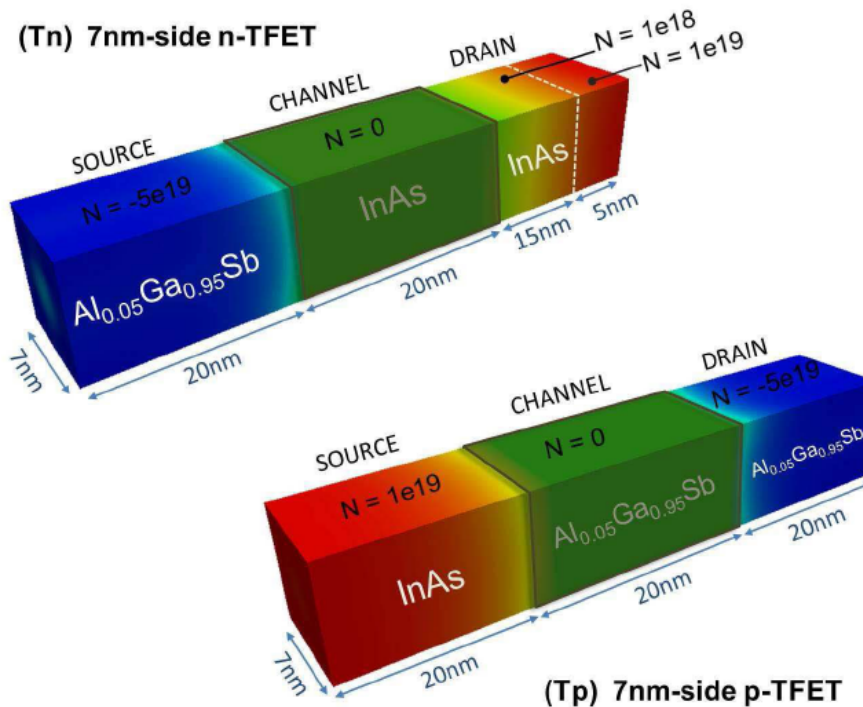
Modeling: UDINE con MC + BTBT (WKB)

Experiments: Dewey et al., IEDM 2011

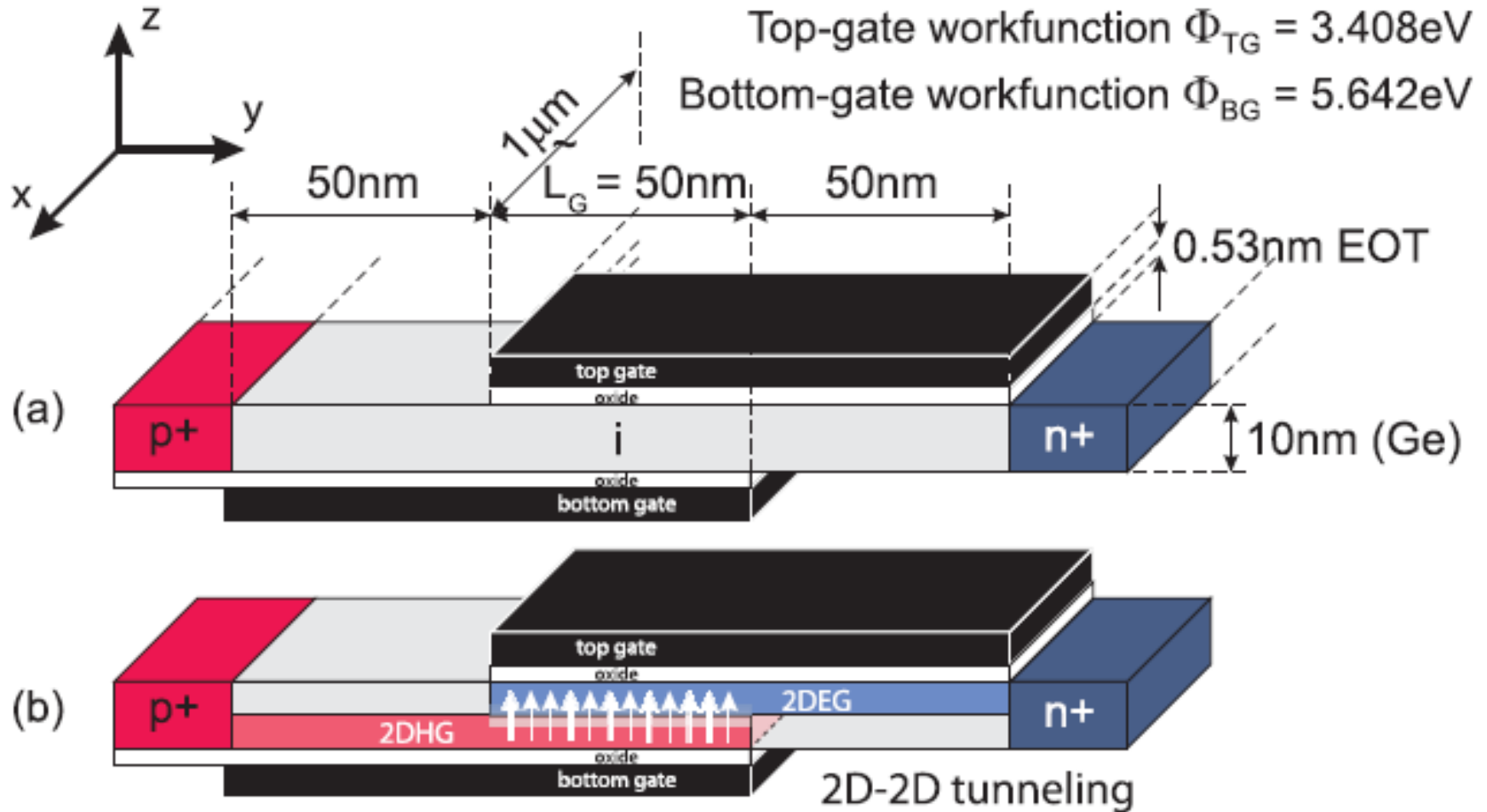


Inverters with InAs/AlGaSb TFETs

- **3D** Full-band quantum simulation with $V_{DD} = 0.25$ V
- **10x faster** than 10 nm FINFET for LOP (same I_{OFF})
- **100x faster** than 10 nm FINFET for LSTP (same I_{OFF})



Ge e-h Bilayer TFET

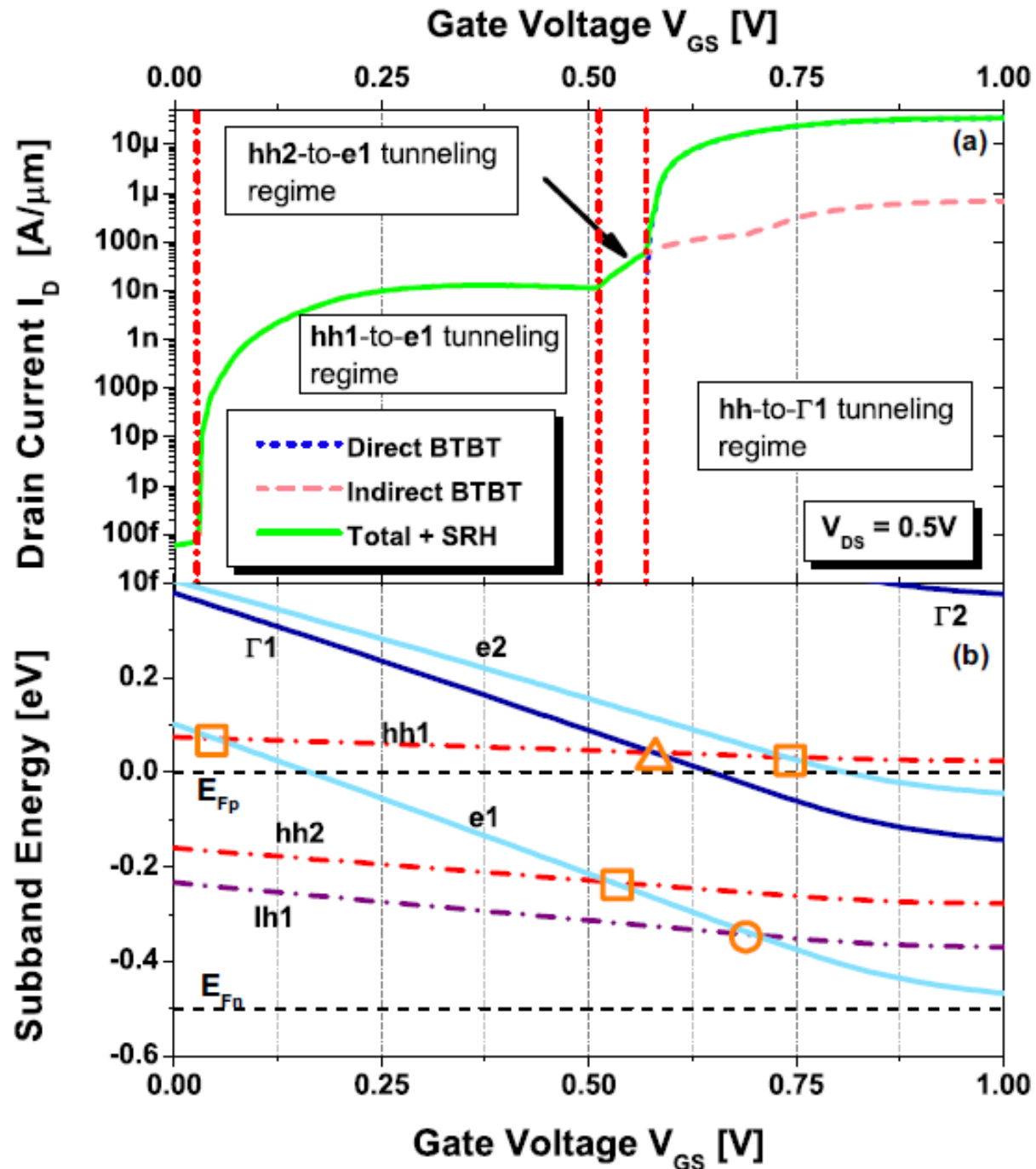


- Tunneling occurs only when subbands are aligned
- Alper et al., TED 60, 2013 (UDINE+EPFL)

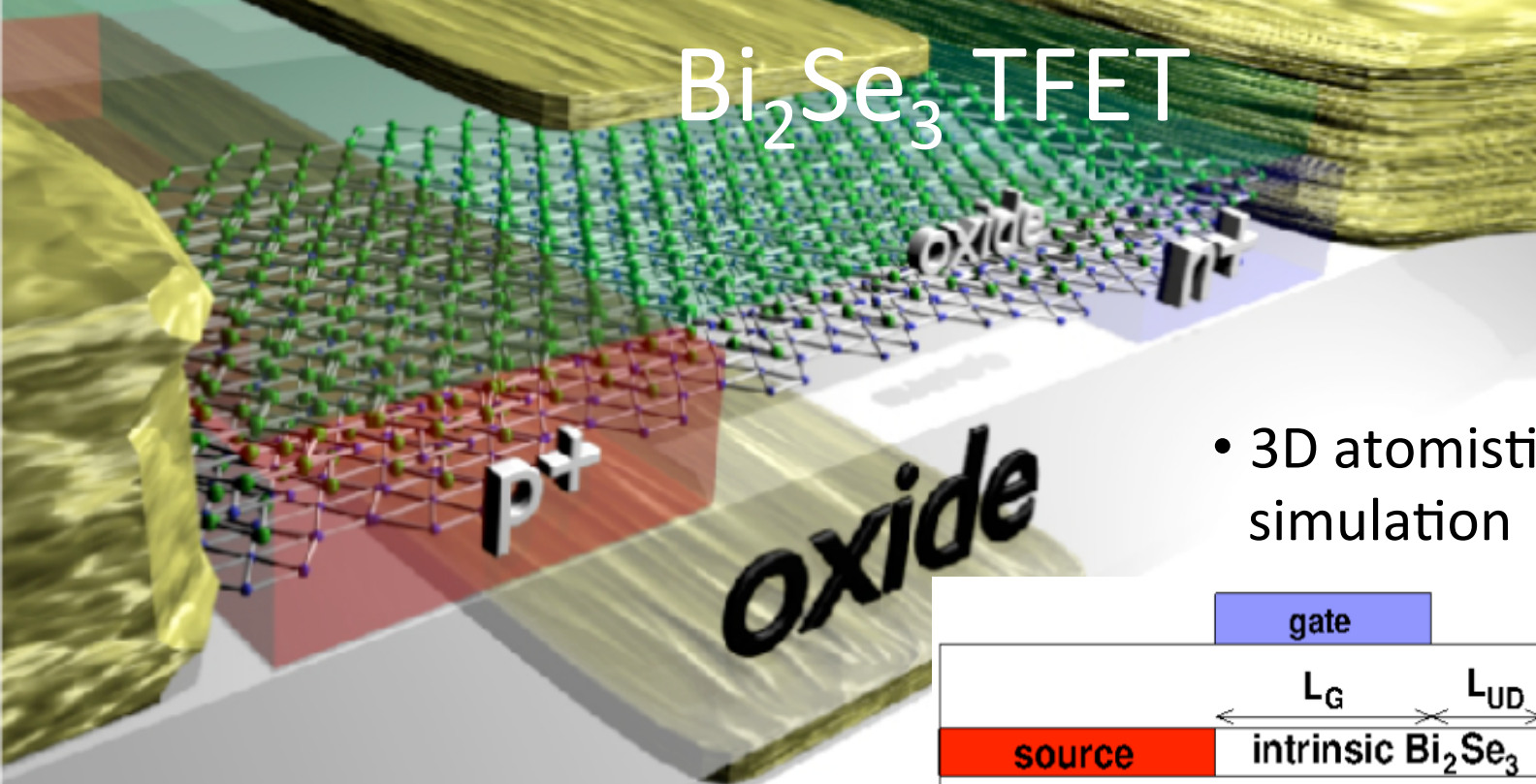
Ge e-h Bilayer TFET

- VB aligns with L \rightarrow ph-assisted BTBT
- VB aligns with Γ \rightarrow direct BTBT
- steep transitions !
- on-current dominated by direct BTBT

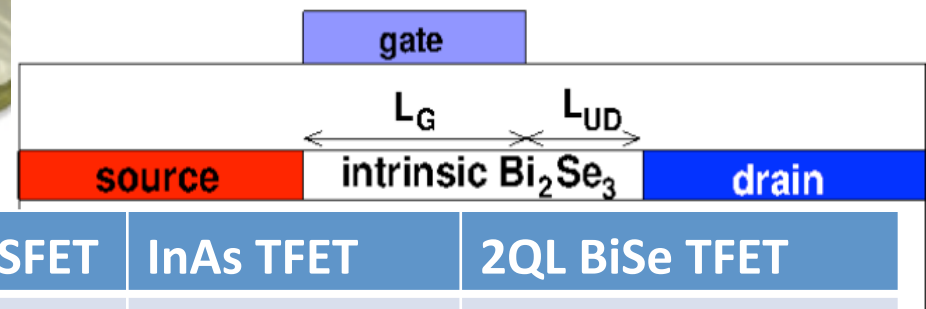
Alper et al., TED 60, 2013 (UDINE+EPFL)



Bi₂Se₃ TFET



- 3D atomistic quantum simulation



	2014 LP MG MOSFET	InAs TFET	2QL BiSe TFET
Ch. length (nm)	13	15	10+15
V _{DD} (V)	0.57	0.3	0.2
I _{ON} (A/m)	794	15	48
DPI (fJ/μm)	0.18		0.018
τ = CV _{DD} /I (ps)	0.4		1.84

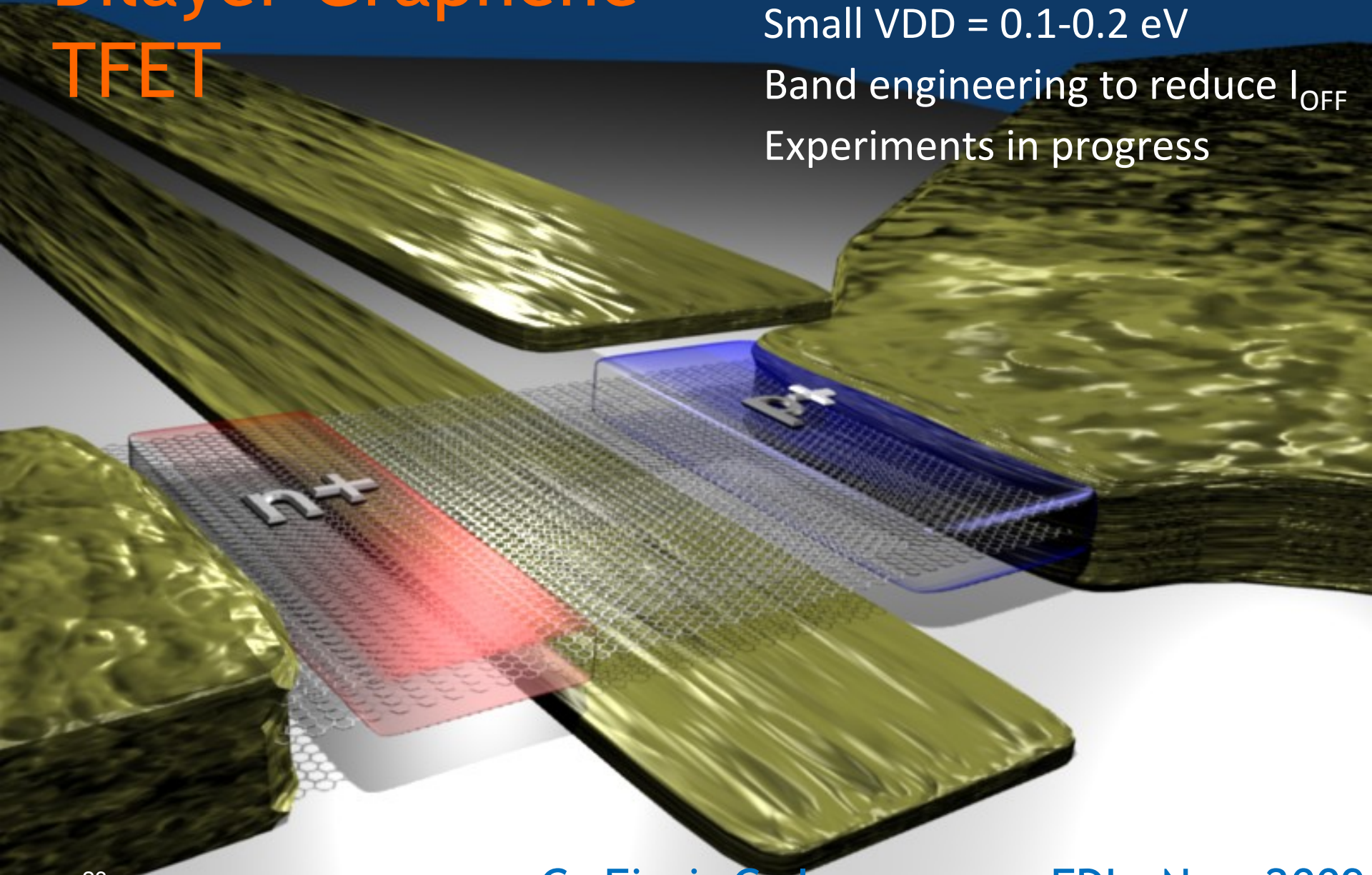
Bilayer Graphene TFET

Energy Gap ~ 0.2 eV

Small VDD = 0.1-0.2 eV

Band engineering to reduce I_{OFF}

Experiments in progress

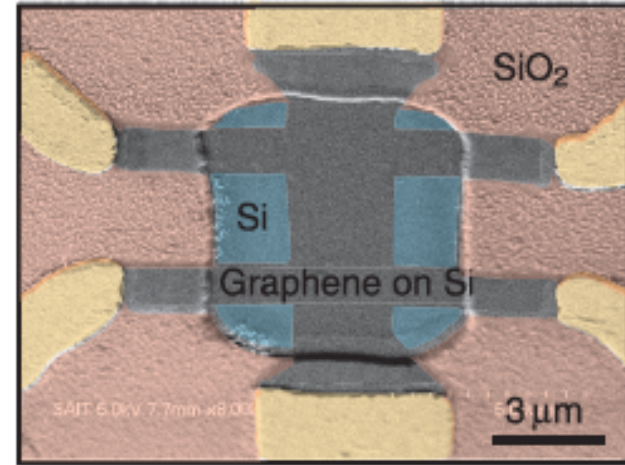
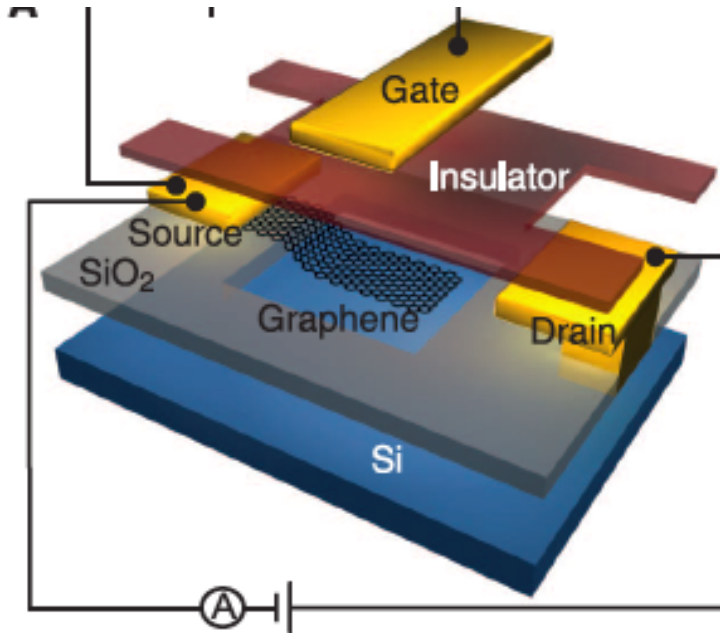


Graphene-based devices

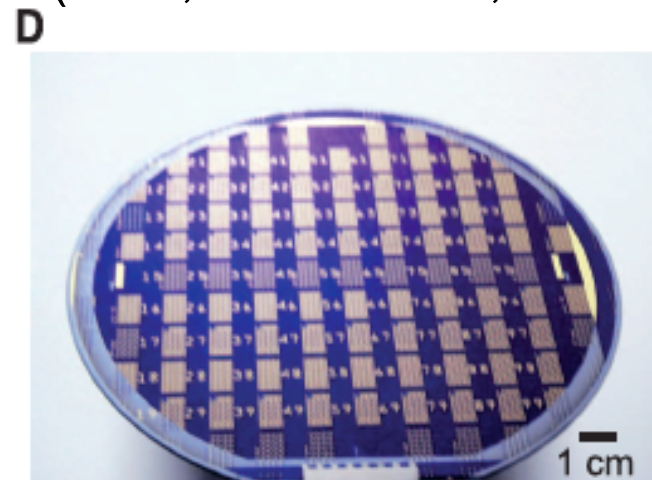
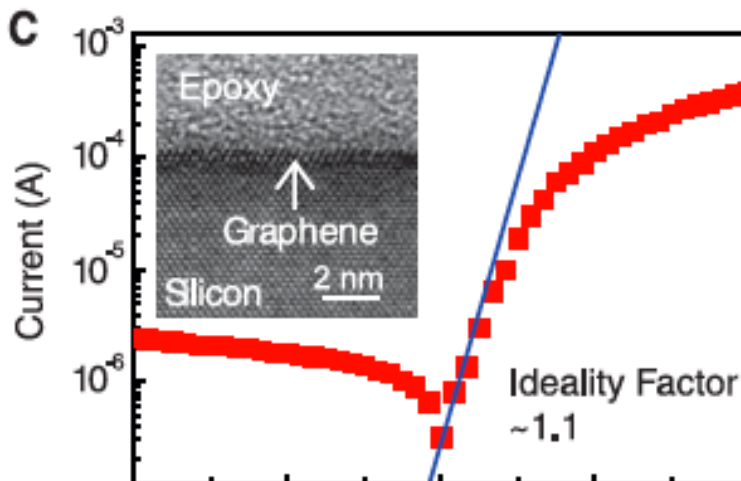
The zero energy gap in graphene is The Problem (transistor cannot be switched off)

- Graphene nanoribbons cannot work;
 - require single-atom control (huge gap variations)
 - have **low mobility**
- Induced gap too small (e.g. bilayer gap < 0.2 eV)
- **Focus on:** Vertical and Lateral Heterostructure Devices

Graphene Barristor



K. Yang, Science 2012
(SAIT, Columbia U., Samsung)



Electron Tunneling through Ultrathin Boron Nitride Crystalline Barriers

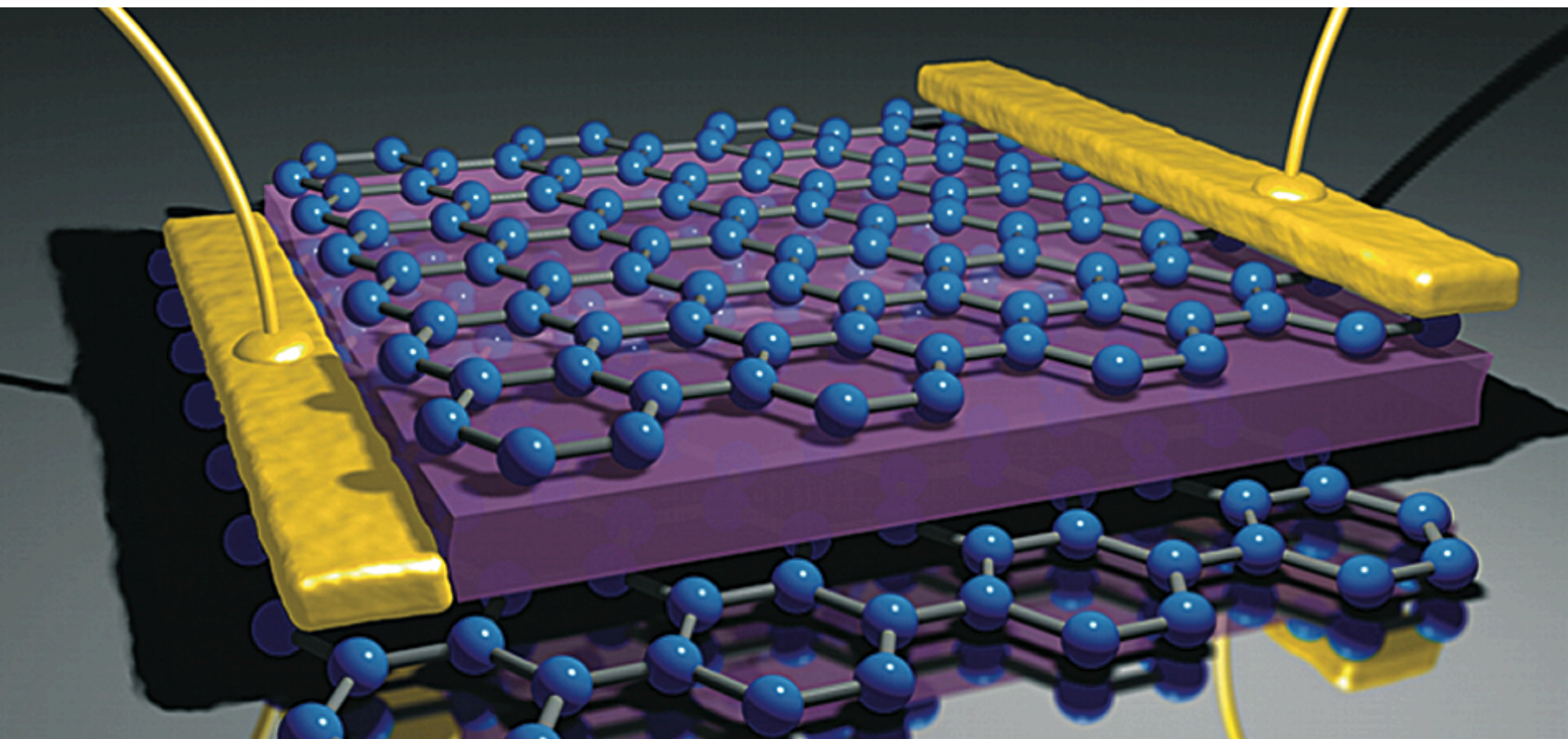
Liam Britnell,[†] Roman V. Gorbachev,[‡] Rashid Jalil,[‡] Branson D. Belle,[‡] Fred Schedin,[‡] Mikhail I. Katsnelson,[§] Laurence Eaves,^{||} Sergey V. Morozov,[⊥] Alexander S. Mayorov,[†] Nuno M. R. Peres,^{#,∇} Antonio H. Castro Neto,[∇] Jon Leist,[◆] Andre K. Geim,^{†,‡} Leonid A. Ponomarenko,[†] and Kostya S. Novoselov^{*,†}

Britnell et al. Nano Letters 2011

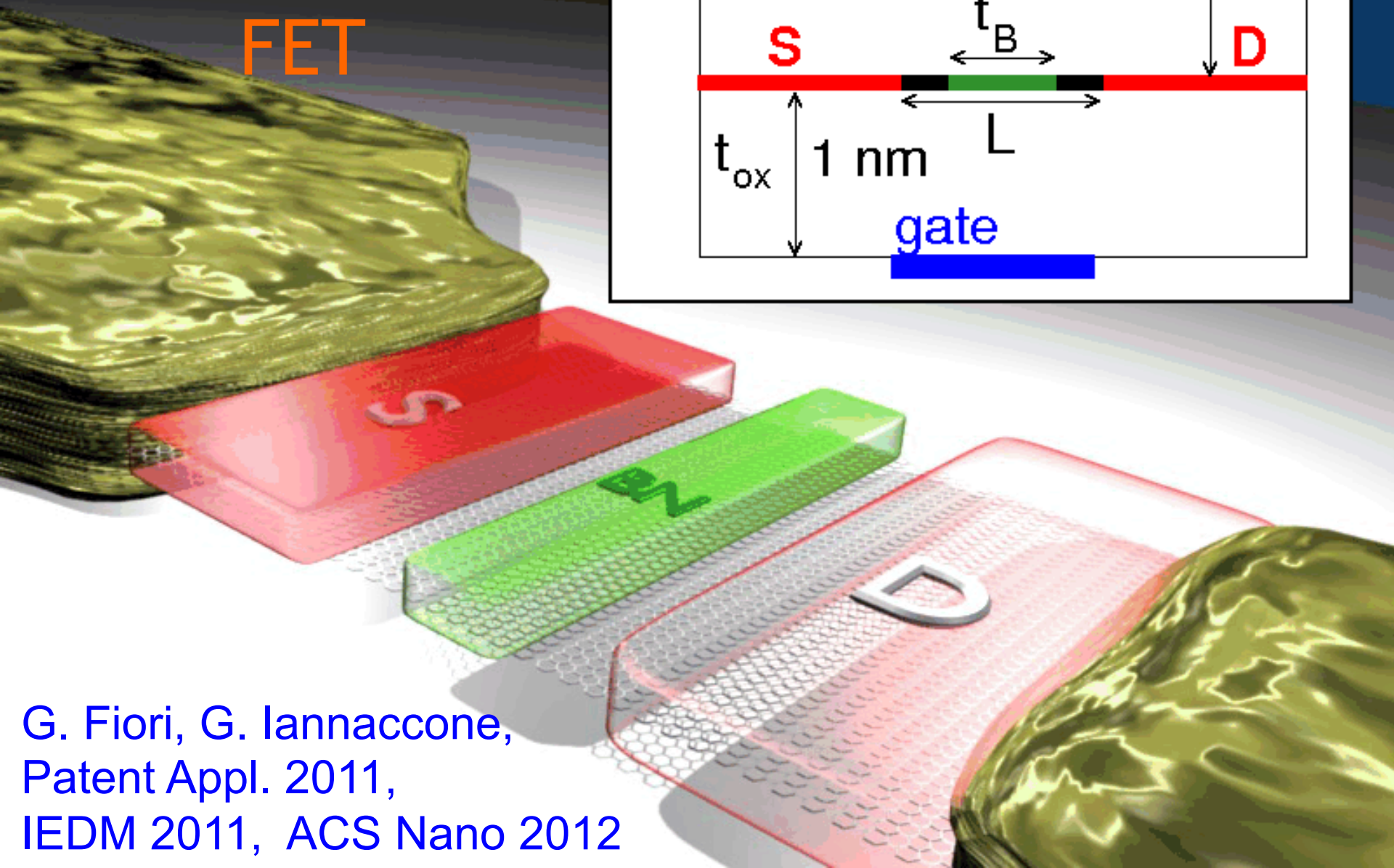
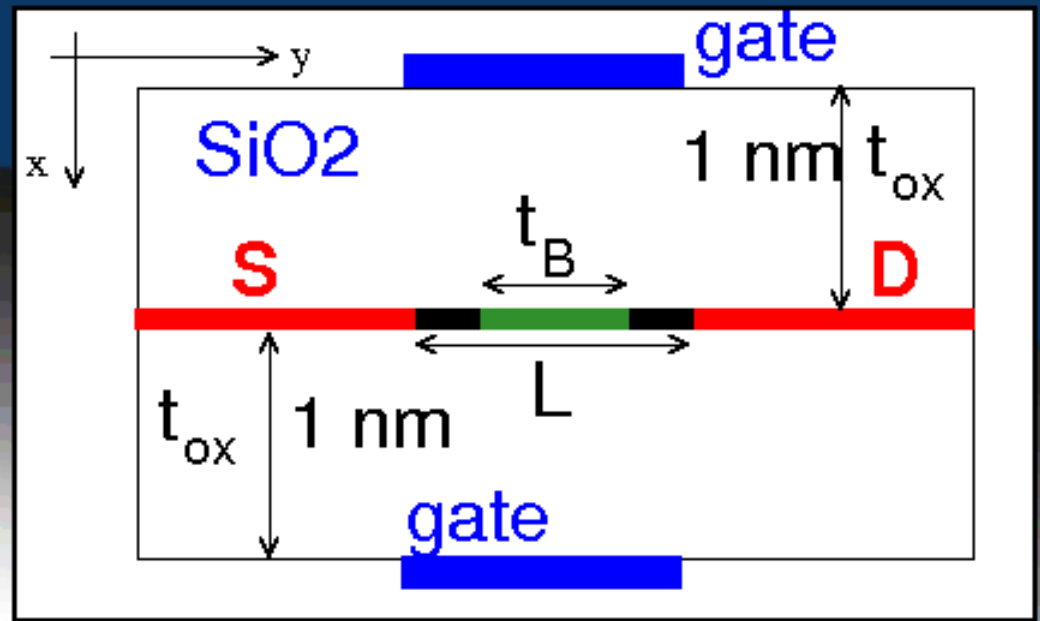
Britnell et al. Science 2011

Field-Effect Tunneling Transistor Based on Vertical Graphene Heterostructures

L. Britnell,¹ R. V. Gorbachev,² R. Jalil,² B. D. Belle,² F. Schedin,² A. Mishchenko,¹ T. Georgiou,¹ M. I. Katsnelson,³ L. Eaves,⁴ S. V. Morozov,⁵ N. M. R. Peres,^{6,7} J. Leist,⁸ A. K. Geim,^{1,2*} K. S. Novoselov,^{1*} L. A. Ponomarenko^{1*}



Lateral heterostructure FET

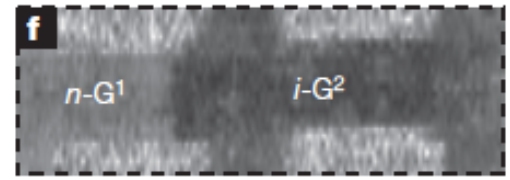
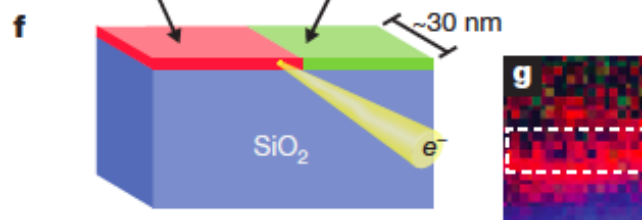
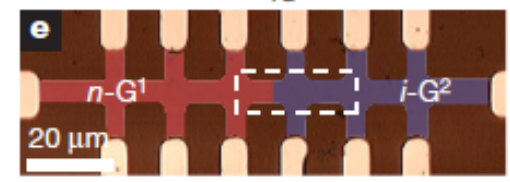
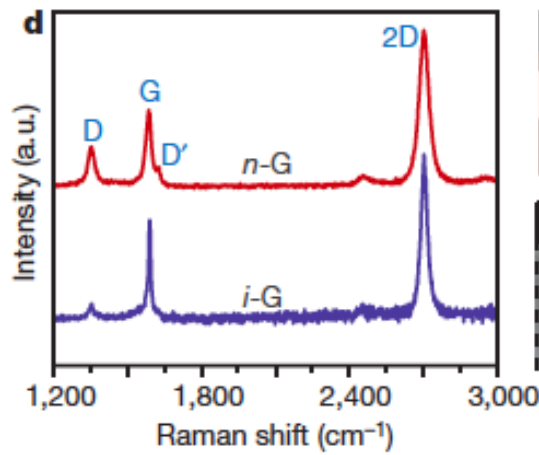
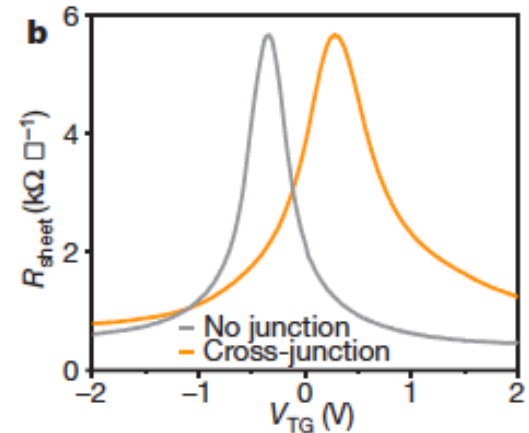
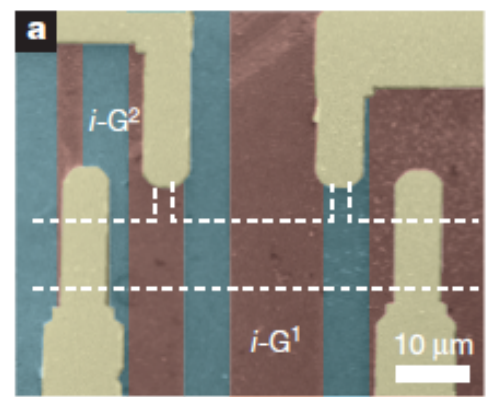
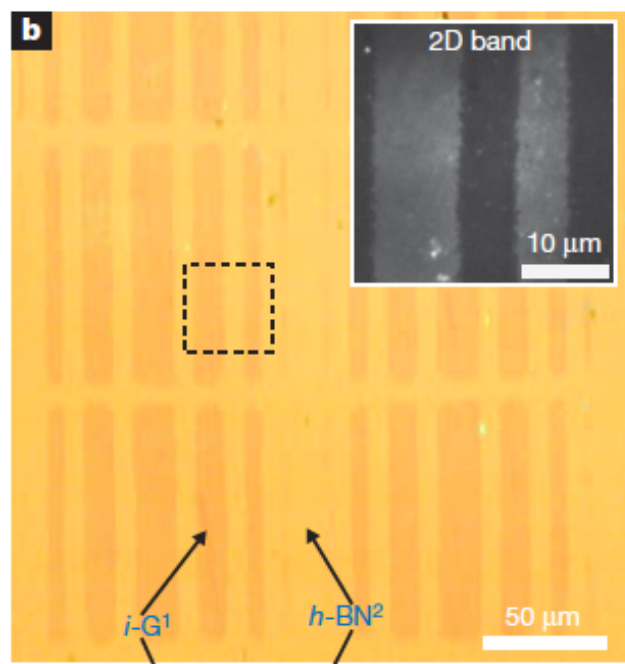


G. Fiori, G. Iannaccone,
Patent Appl. 2011,
IEDM 2011, ACS Nano 2012

Lateral G-BN Heterostructures

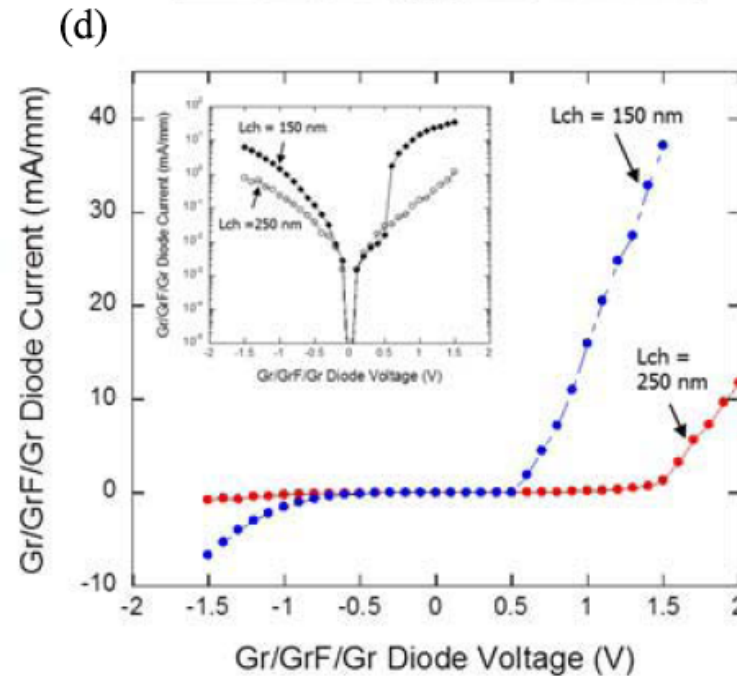
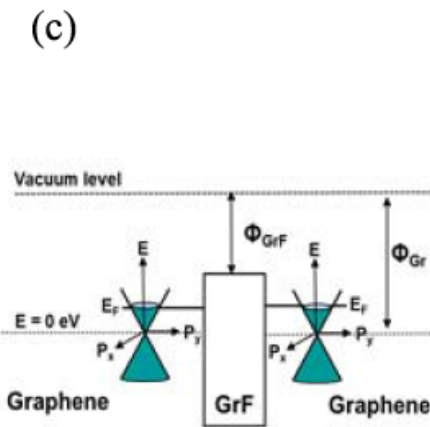
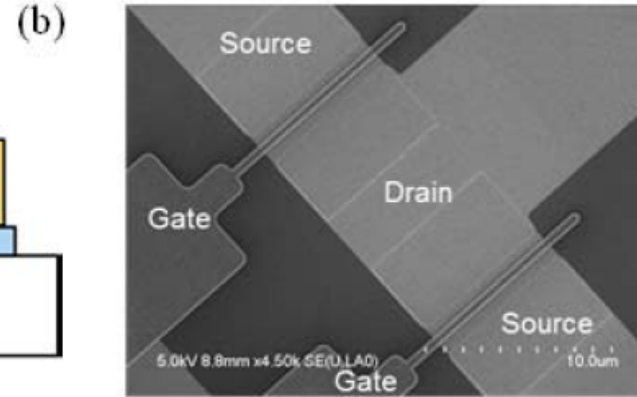
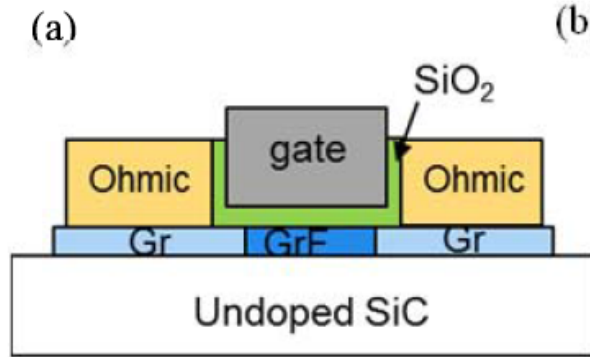


M.P. Levendovf
Nature 2012
(Cornell)



LHFET Experimental Demonstration

Moon et al. (HRL), EDL 34, 1190, 2013



Multi-scale Modeling

A multi-scale approach for the simulation of nanoscale devices with self-extraction of tight-binding parameters from ab-initio simulations

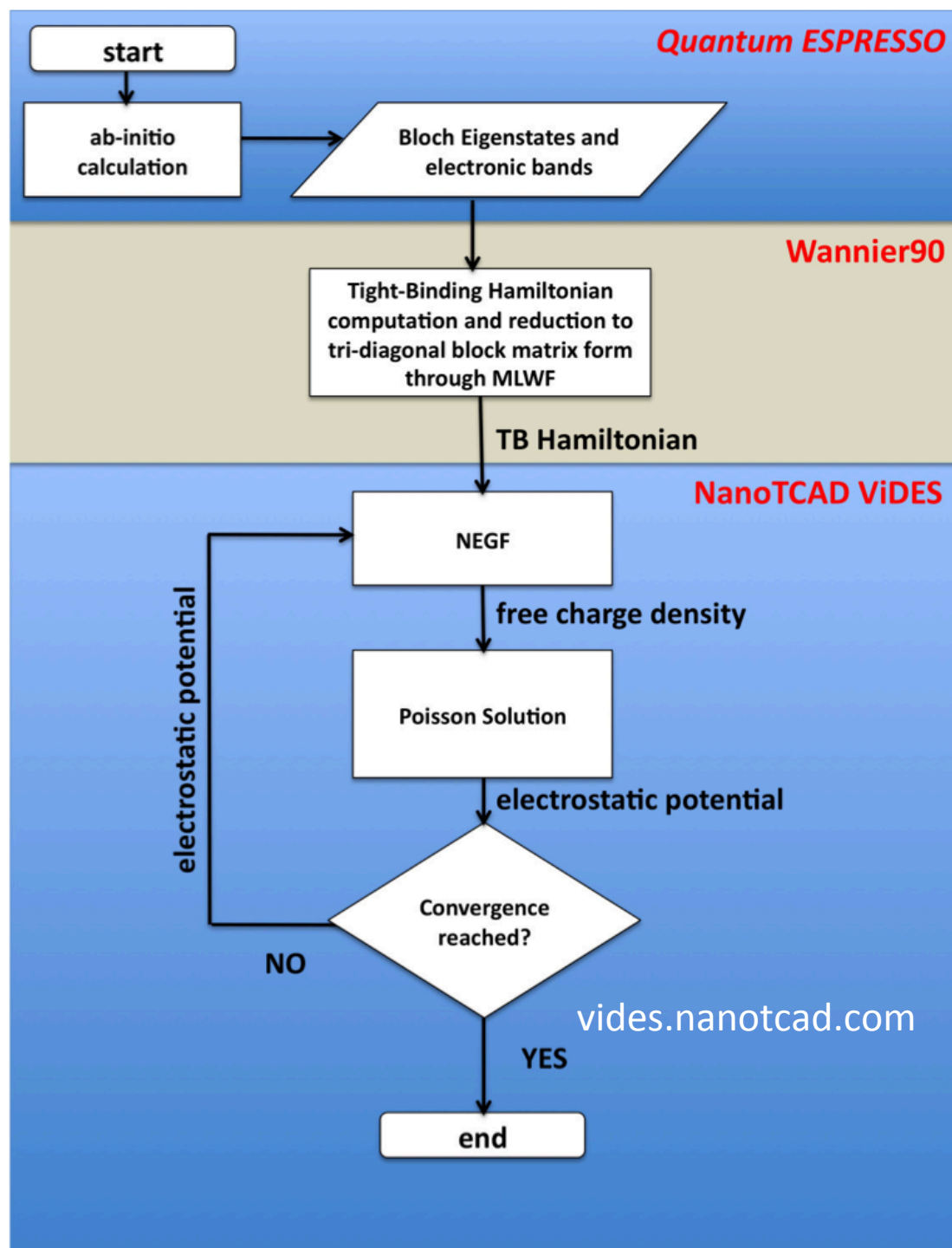
1. DFT (Materials modeling)

Quantum Espresso

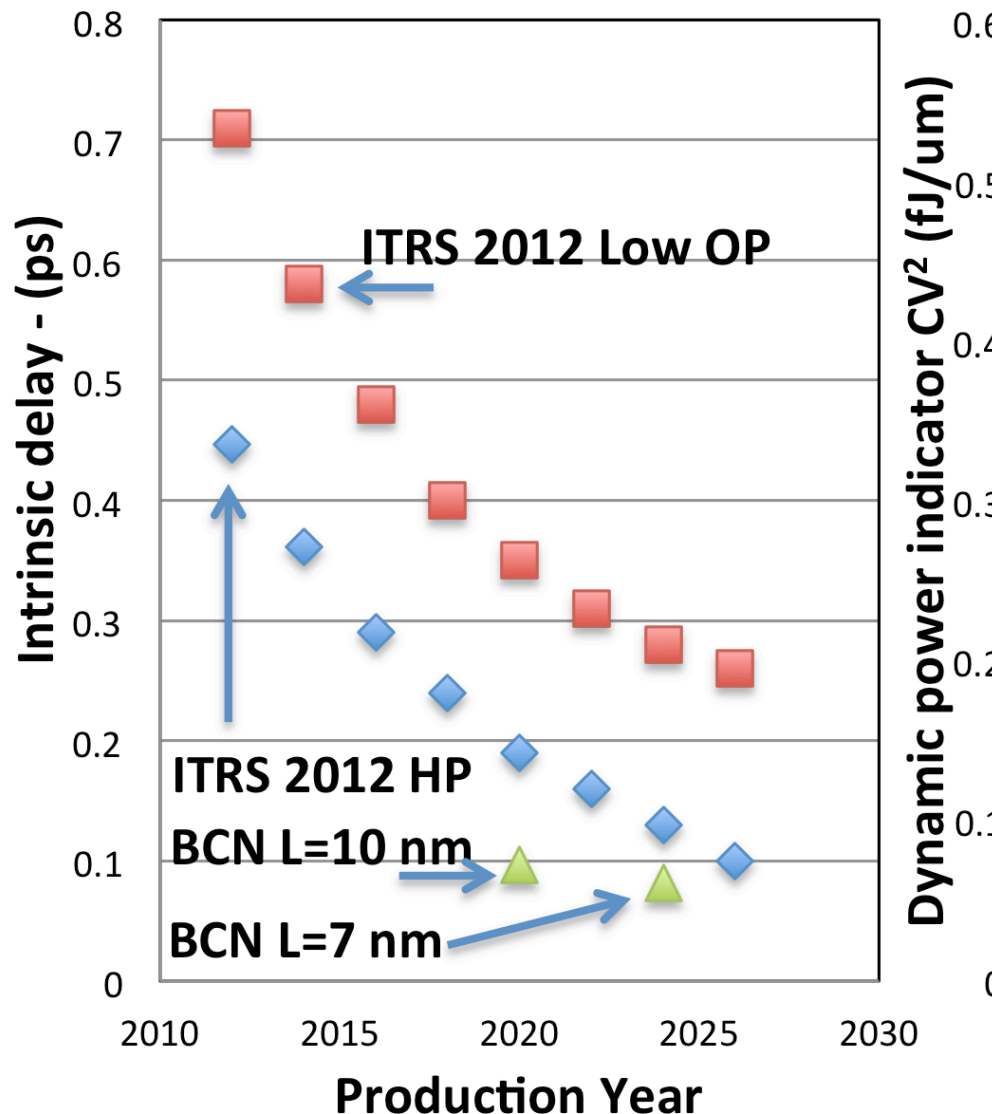
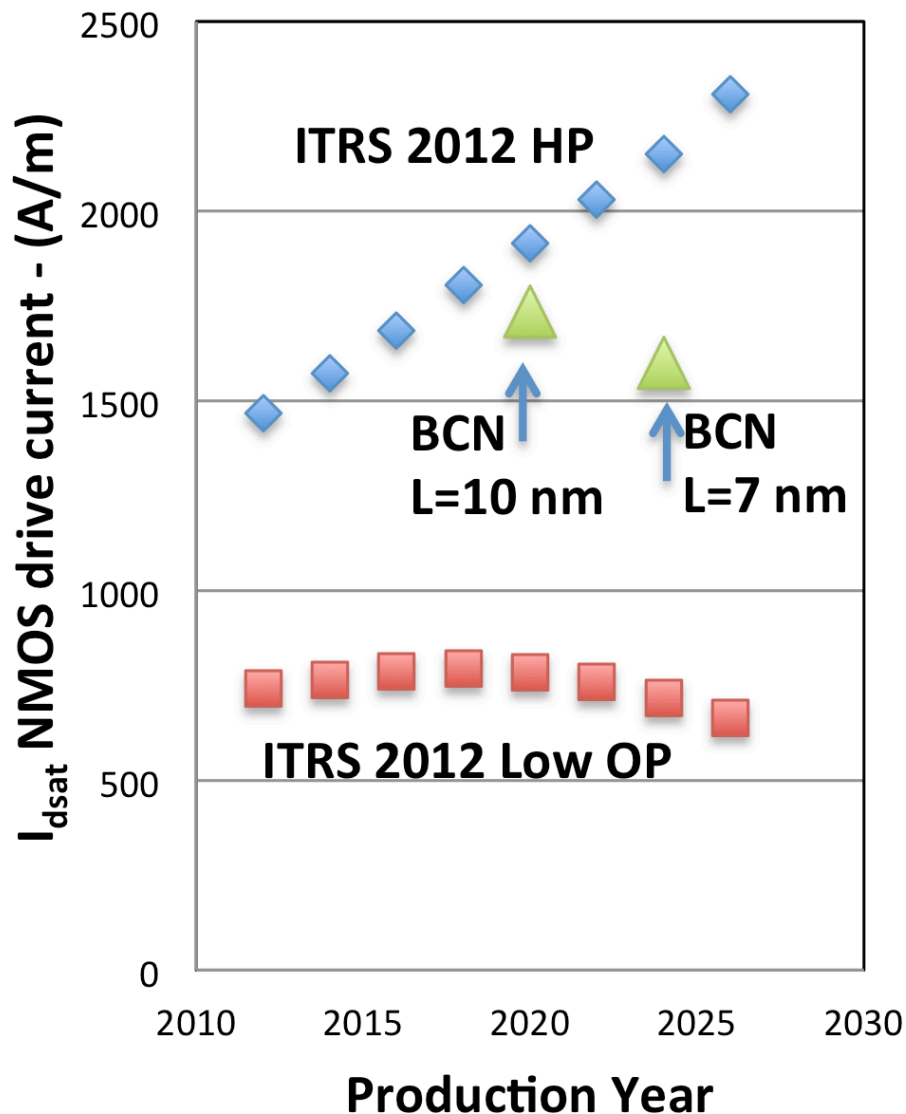
2. Wannier 90

3. NEGF-TB

NanoTCAD ViDES



Graphene LHFET - vs ITRS 2012

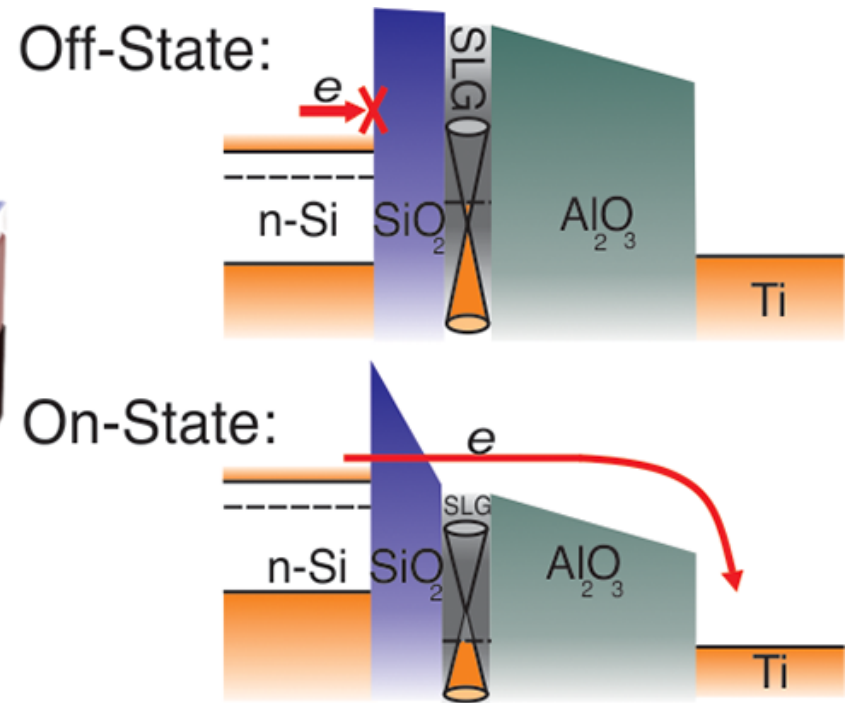
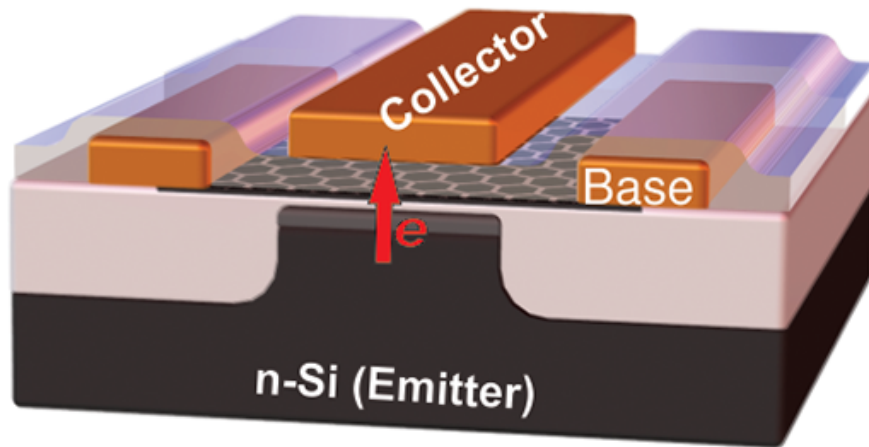


VHFET: $\tau = 625$ ps

Barristor: $\tau = 160$ ps

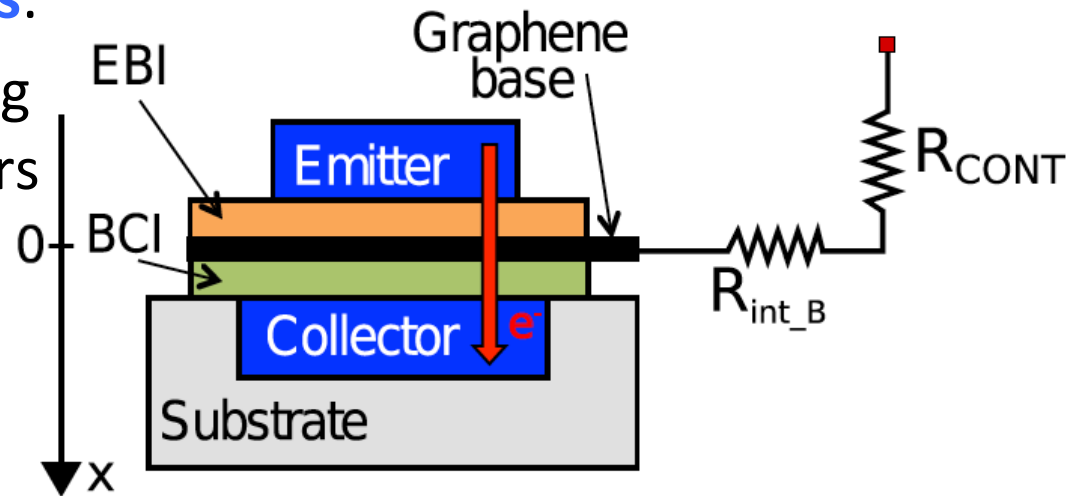
Graphene-base hot electron transistor

S. Vaziri et al.
(KTH, U. Siegen, IHP)
Nano Letters 2012



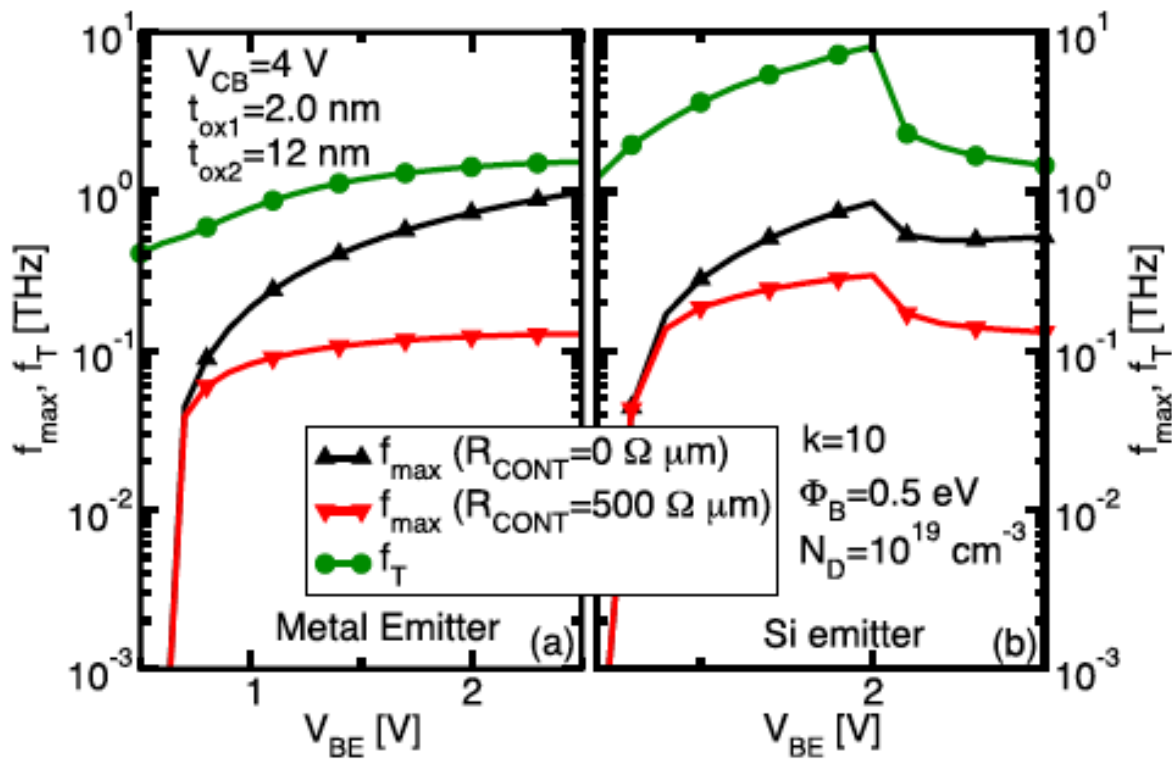
Optimized design of the GBT

- 1D model for GBT electrostatic and currents
- **Self consistent Electrostatics:**
- **Tunnelling currents** including Energy distribution of carriers in emitter and base accounted for
- **Cut-off frequency (f_T)** estimated with quasi-static approach
- **Montecarlo model for the simulation of base current in GBTs**



S. Venica et al. TED 61, 2570 (2014)
- UDINE

GBT optimization



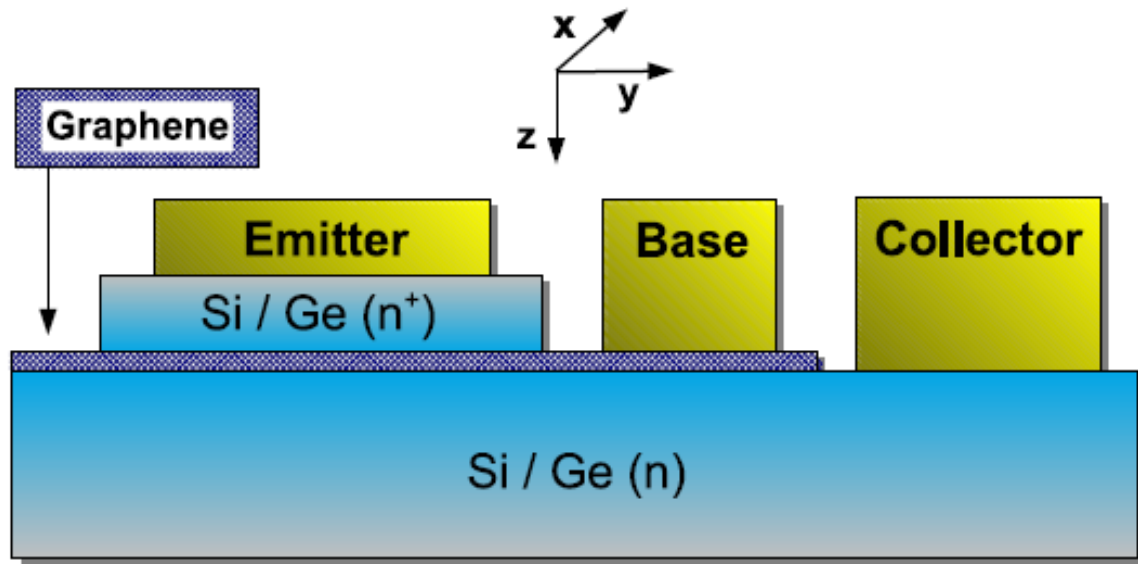
	DEV. 1	DEV. 2
Emitter	Si $N_D = 10^{19} \text{ cm}^{-3}$	Ti $\Phi_{M1} = 4.33 \text{ eV}$
EBI	Ta_2O_5	SiCOH
BCI	Ta_2O_5	SiCOH
$k [\epsilon_0]$	25	2.5
$\Phi_{B1} [\text{eV}]$	0.36	0.53
$\Phi_{M2} [\text{eV}]$	4.33	4.33

- **THz operation possible**
- **Si emitter GBT** → Si band bending lowers EBI → Larger band bending for larger k value
- **Metal emitter GBT** → lower k results in lower capacitance

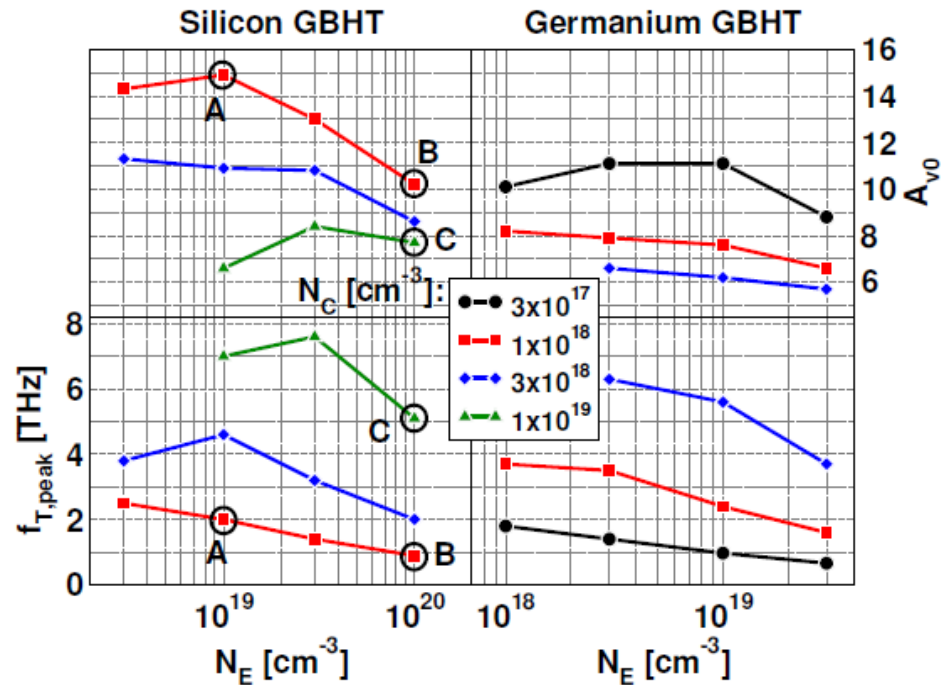
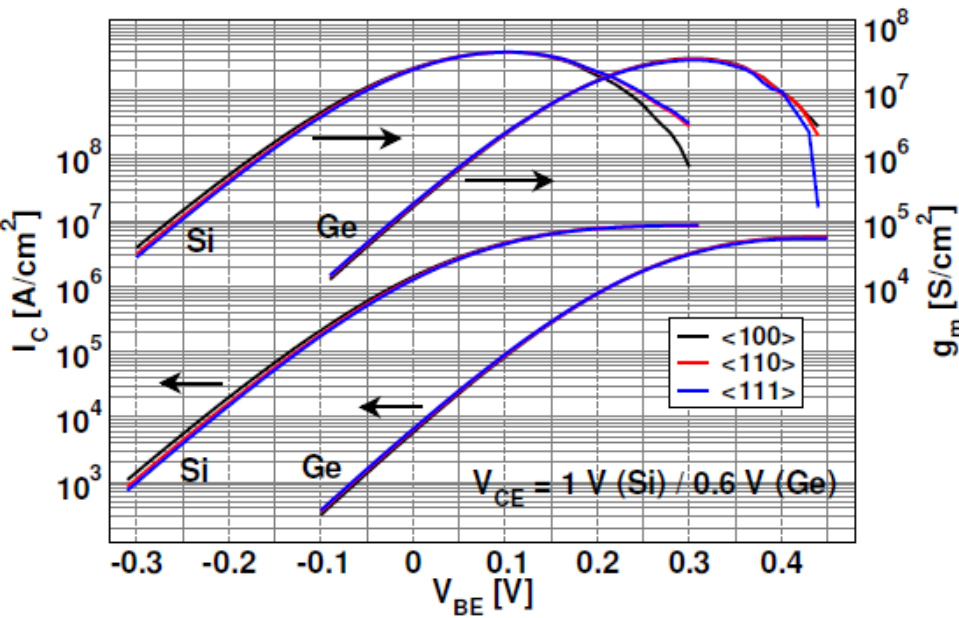
S. Venica et al. TED 61, 2570 (2014)

Graphene Base Heterojunction Transistor (GBHT)

- Impact of different orientations and materials (Si/Ge)
- Sensitivity to doping concentrations
- Effect of graphene base resistance (f_{MAX})
- Inclusion of ionized impurity scattering in Si



GHBT Impact of doping, materials

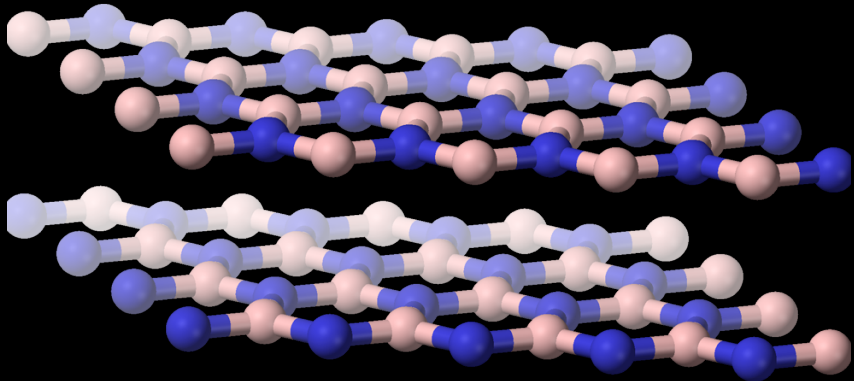


- **THz Operation Possible**

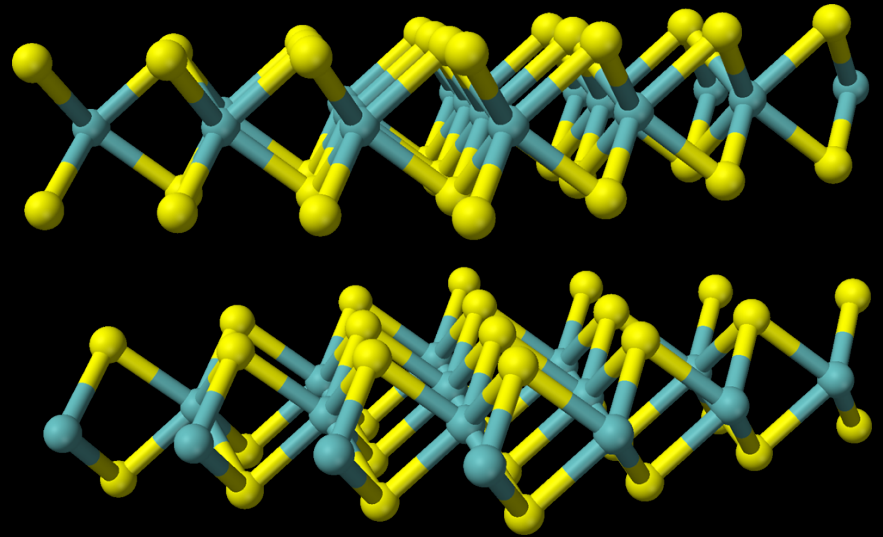
- Si and Ge provide comparable performance

V. Di Lecce et al. , TED60, 4263 (2013)

Other 2D materials

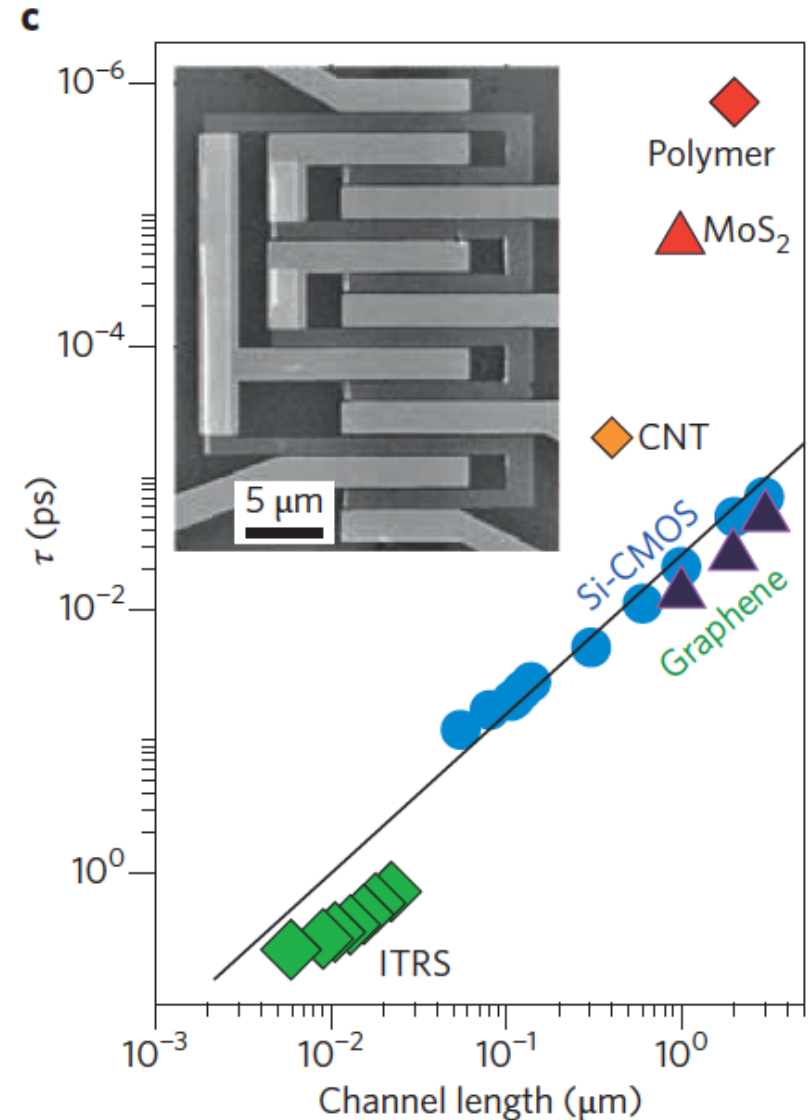
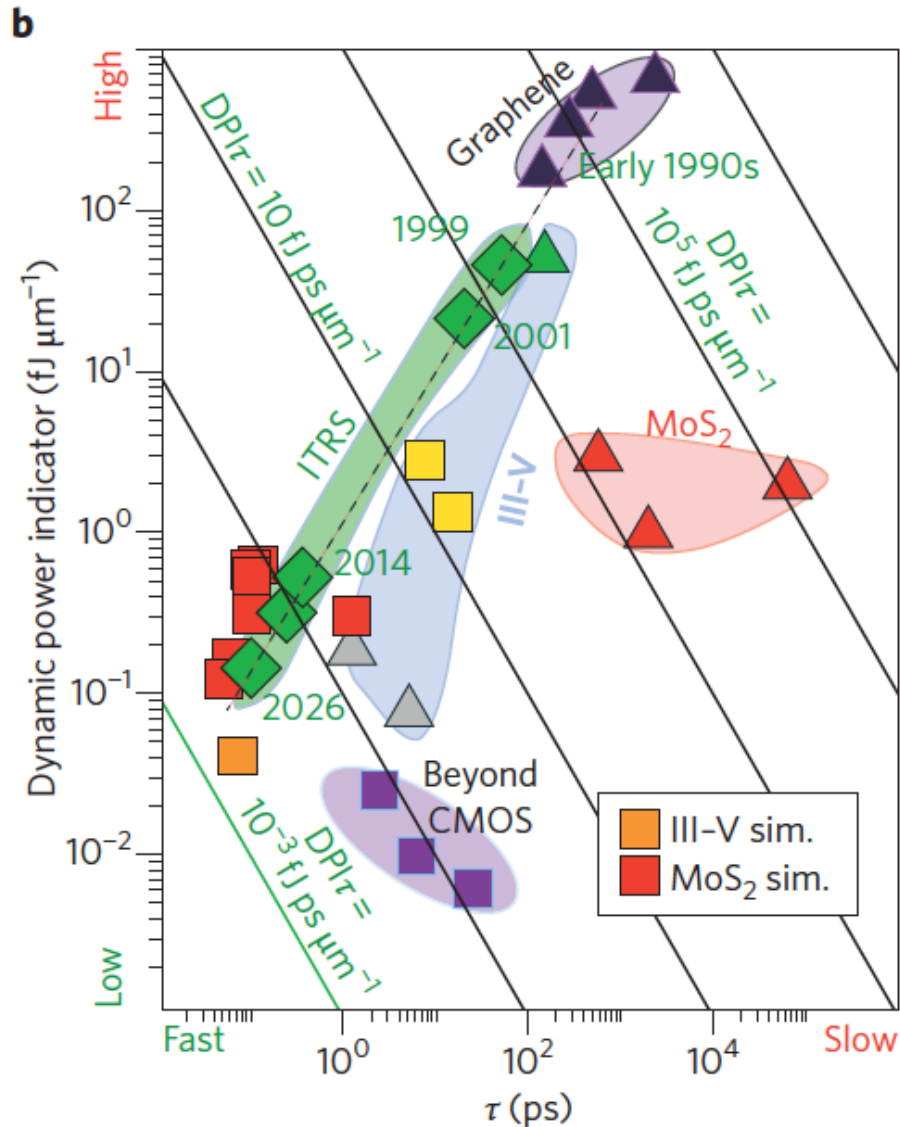


Boron Nitride

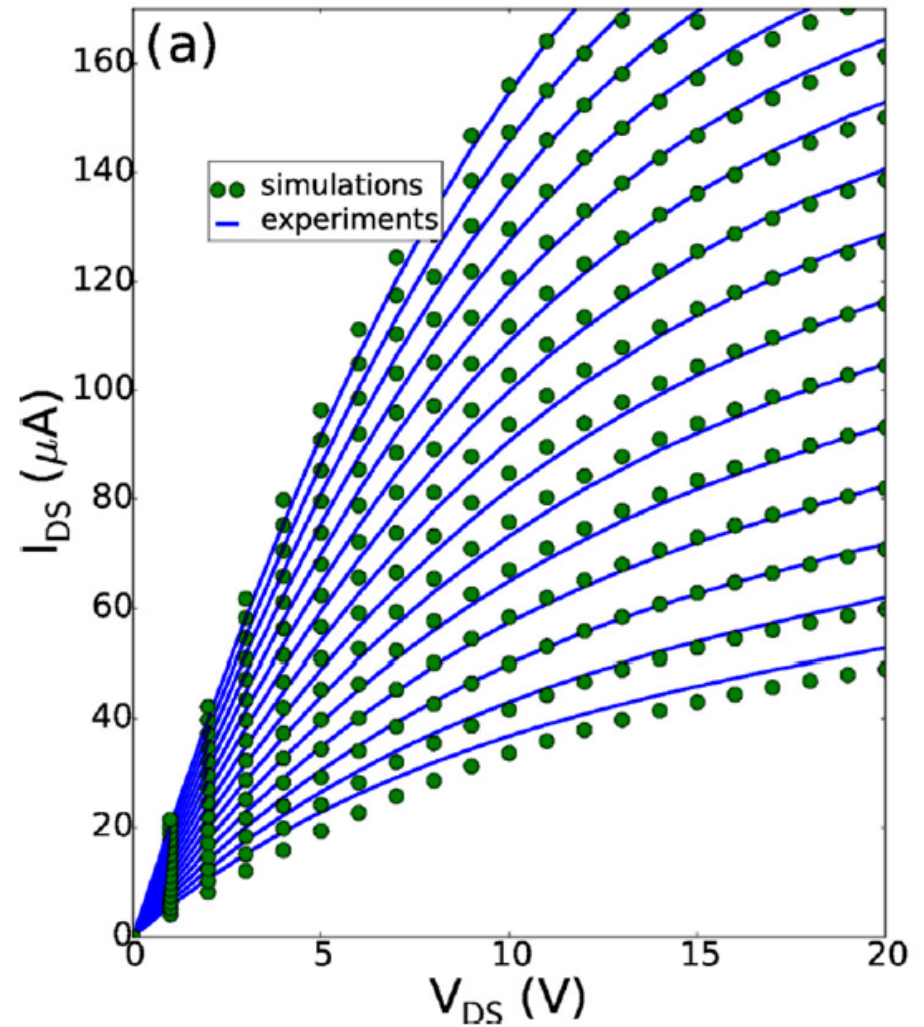
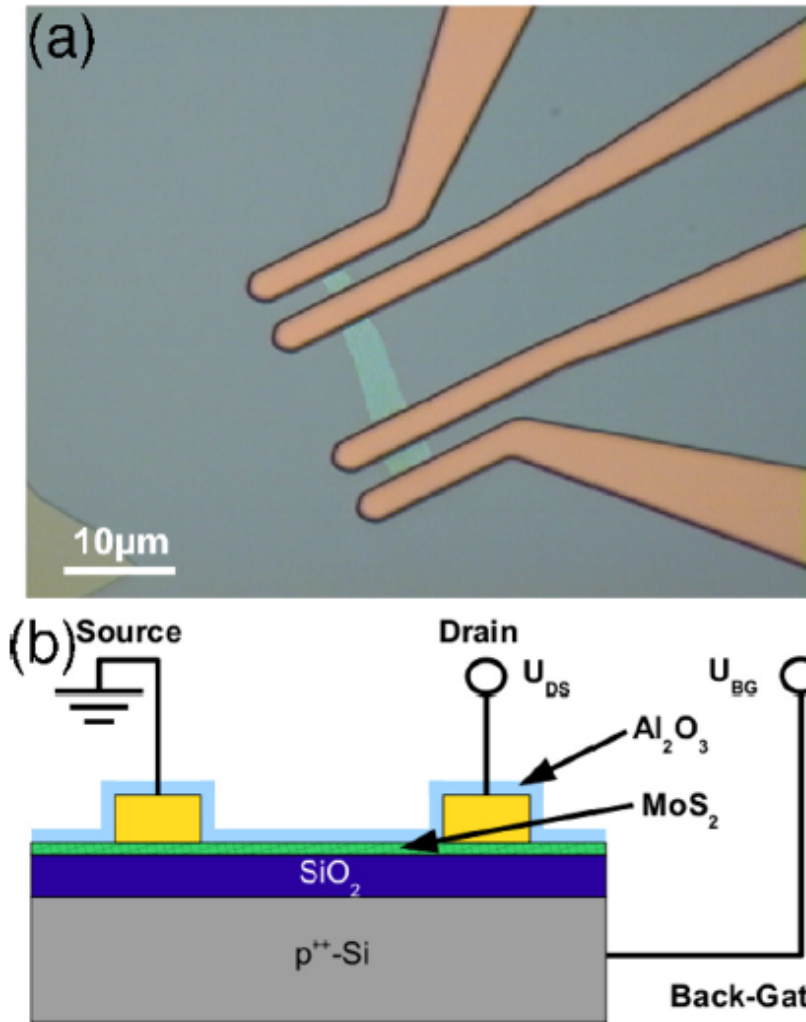


Molybdenum disulfide

Next – other 2D materials ?



Velocity saturation in MoS₂



All in “Beyond CMOS”

Giorgio Baccarani
Emanuele Baravelli
Alessandro Betti
Giovanni Betti Beneventi
Samantha Bruzzone
Martina Cheli
Teresa Cusati
Valerio Di Lecce
Francesco Driussi
David Esseni
Gianluca Fiori
Elena Gnani
Antonio Gnudi
Roberto Grassi
Giuseppe Iannaccone
Demetrio Logoteta
Massimo Macucci
Paolo Marconcini

Paolo Michetti
Pierpaolo Palestri
Susanna Reggiani
Luca Selmi
Stefano Venica
Qin Zhang

**+ Several colleagues from
Academia and Industry**

Funding projects:

FP7 GRADE

FP7 STEEPER

FP7 GRAND

FP7 NANOSIL

H2020 E2SWITCH

MIUR GRANFET



Thank you